



US00D619969S

(12) **United States Design Patent**  
**Apfelbacher et al.**

(10) **Patent No.:** **US D619,969 S**  
(45) **Date of Patent:** **\*\* Jul. 20, 2010**

(54) **SEMICONDUCTOR BASED SWITCHING DEVICE**

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(73) Assignee: **Siemens Aktiengesellschaft**, Munich (DE)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/272,945**

(22) Filed: **Feb. 23, 2007**

(30) **Foreign Application Priority Data**

Aug. 23, 2006 (EM) ..... 000585120

(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/159**

(58) **Field of Classification Search** ..... D13/123-126,  
D13/159, 182, 184, 199; 200/280, 303, 293,  
200/294, 297; 331/131, 132, 133, 202, 196,  
331/262, 251

See application file for complete search history.

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*Primary Examiner*—Daniel D Bui

*Assistant Examiner*—Thomas J Johannes

(74) *Attorney, Agent, or Firm*—Harness, Dickey & Pierce, P.L.C.

(57) **CLAIM**

The ornamental design for a semiconductor based switching device, as shown.

**DESCRIPTION**

FIG. 1 is a front elevational view of a first embodiment of a semiconductor based switching device showing our new design;

FIG. 2 is rear elevational view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

FIG. 5 is a right side elevational view thereof;

FIG. 6 is a left side elevational view thereof;

FIG. 7 is a perspective view thereof;

FIG. 8 is a front elevational view of a second embodiment of a semiconductor based switching device showing our new design;

FIG. 9 is rear elevational view thereof;

FIG. 10 is a top plan view thereof;

FIG. 11 is a bottom plan view thereof;

FIG. 12 is a right side elevational view thereof;

FIG. 13 is a left side elevational view thereof;

FIG. 14 is a perspective view thereof;

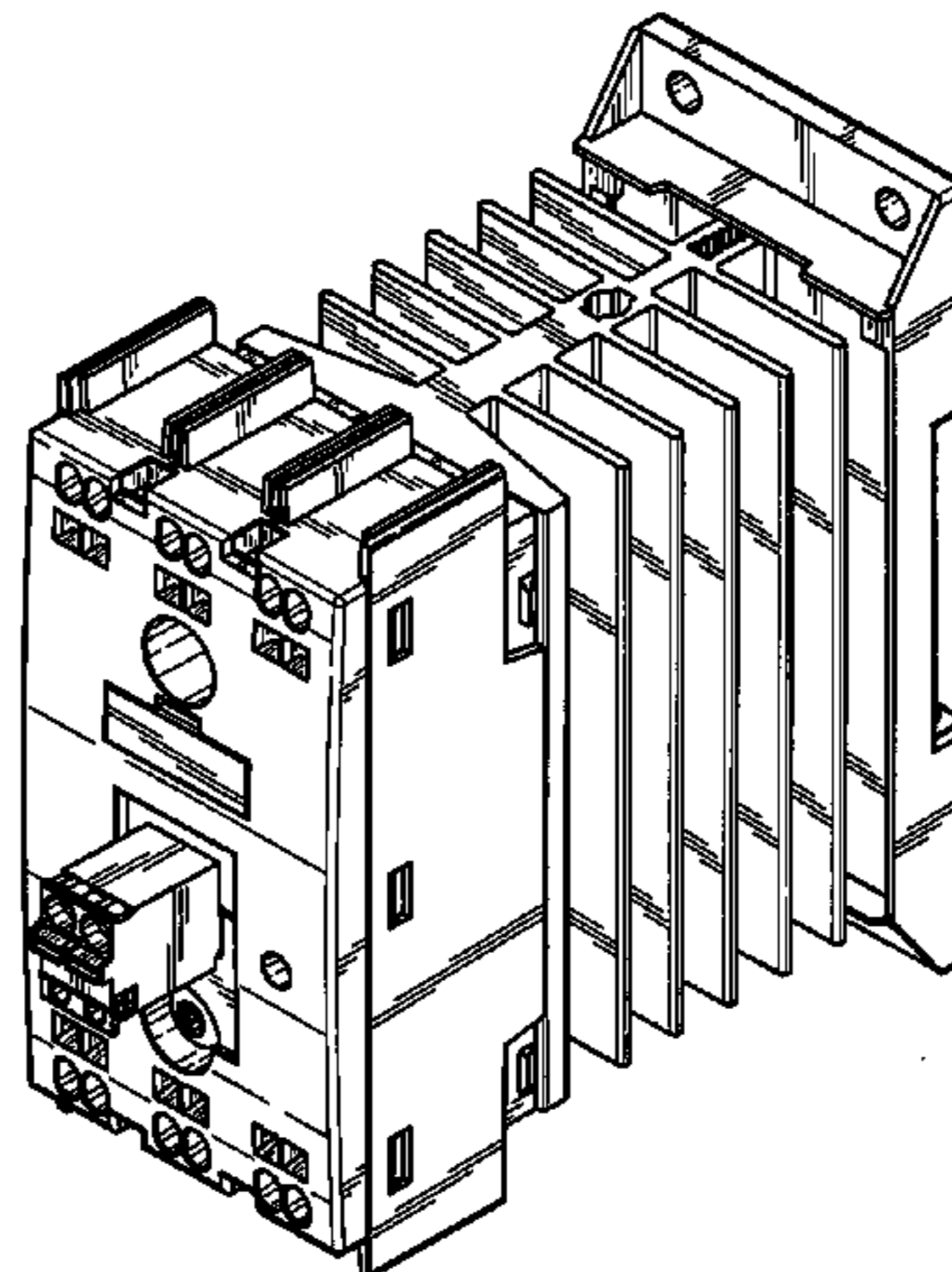
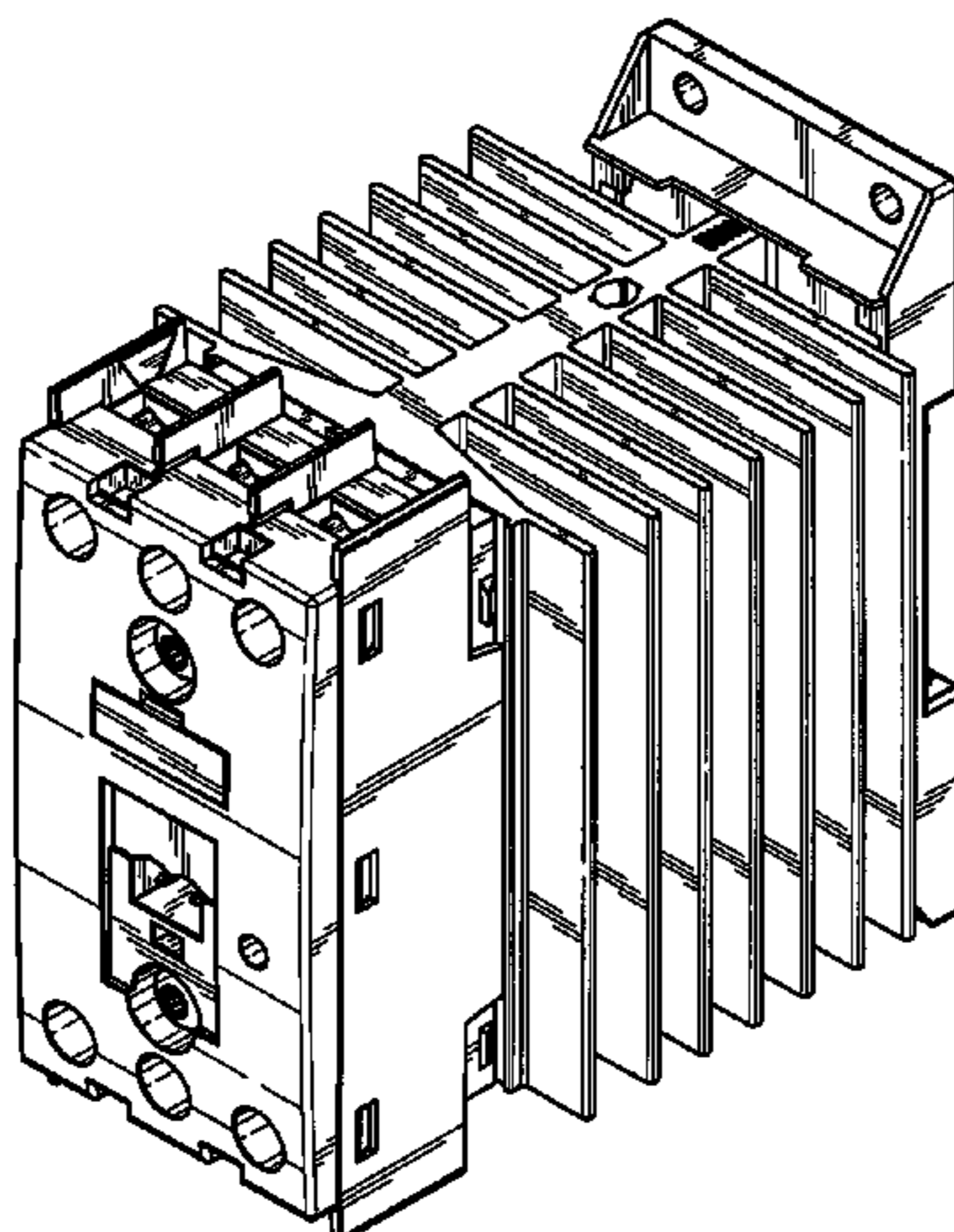


FIG. 15 is a front elevational view of a third embodiment of a semiconductor based switching device showing our new design;

FIG. 16 is rear elevational view thereof;

FIG. 17 is a bottom plan view thereof;

FIG. 18 is a top plan view thereof;

FIG. 19 is a right side elevational view thereof;

FIG. 20 is a left side elevational view thereof;

FIG. 21 is a perspective view thereof;

FIG. 22 is a front elevational view of a fourth embodiment of a semiconductor based switching device showing our new design;

FIG. 23 is rear elevational view thereof;

FIG. 24 is a bottom plan view thereof;

FIG. 25 is a top plan view thereof;

FIG. 26 is a right side elevational view thereof;

FIG. 27 is a left side elevational view thereof;

FIG. 28 is a perspective view thereof;

FIG. 29 is a front elevational view of a fifth embodiment of a semiconductor based switching device showing our new design;

FIG. 30 is rear elevational view thereof;

FIG. 31 is a top plan view thereof;

FIG. 32 is a bottom plan view thereof;

FIG. 33 is a right side elevational view thereof;

FIG. 34 is a left side elevational view thereof;

FIG. 35 is a perspective view thereof;

FIG. 36 is a front elevational view of a sixth embodiment of a semiconductor based switching device showing our new design;

FIG. 37 is rear elevational view thereof;

FIG. 38 is a top plan view thereof;

FIG. 39 is a bottom plan view thereof;

FIG. 40 is a right side elevational view thereof;

FIG. 41 is a left side elevational view thereof; and,

FIG. 42 is a perspective view thereof.

The broken line portion of the figure drawings is included to show unclaimed subject matter only and forms no part of the claimed design.

**1 Claim, 42 Drawing Sheets**

FIG 1

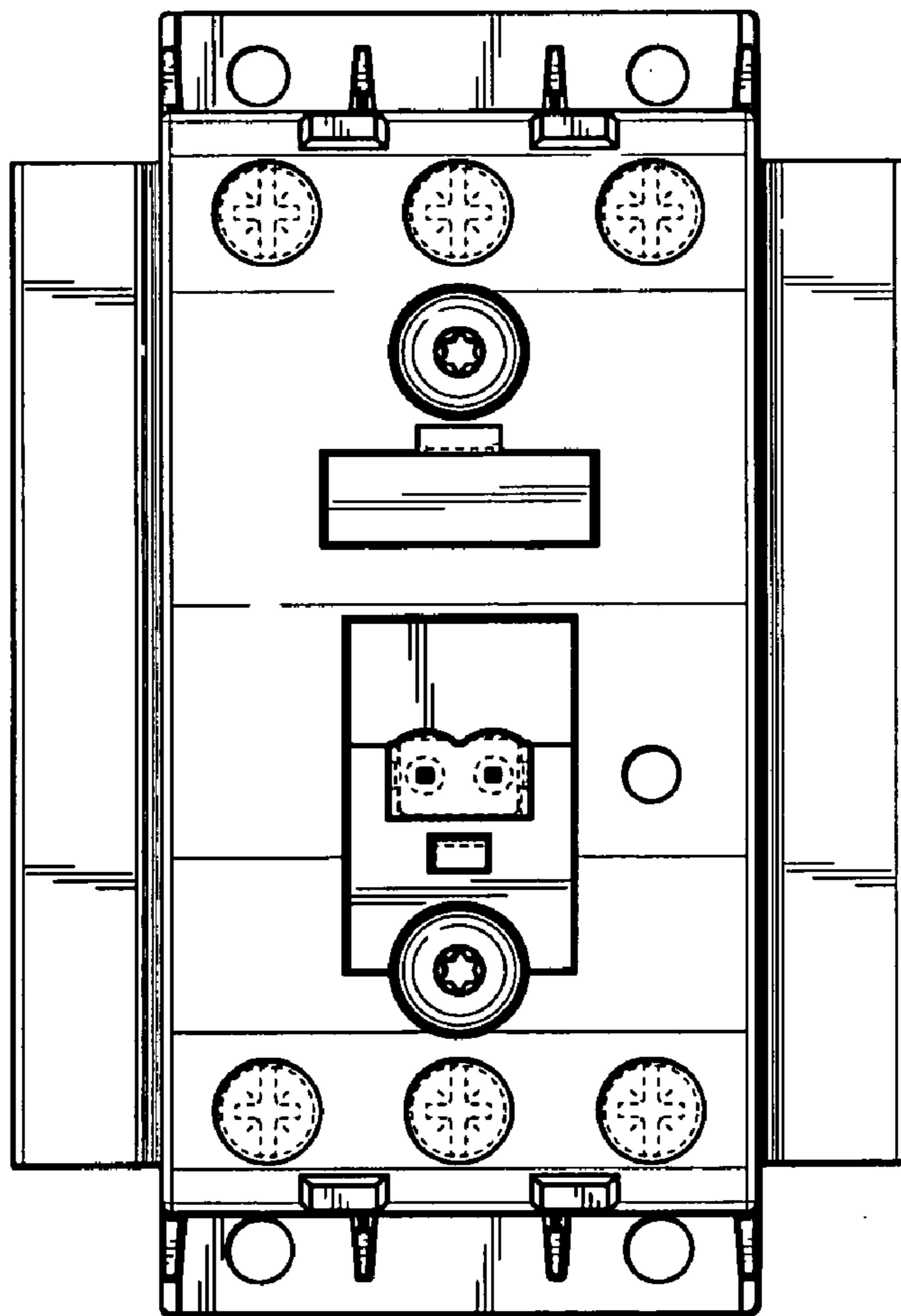


FIG 2

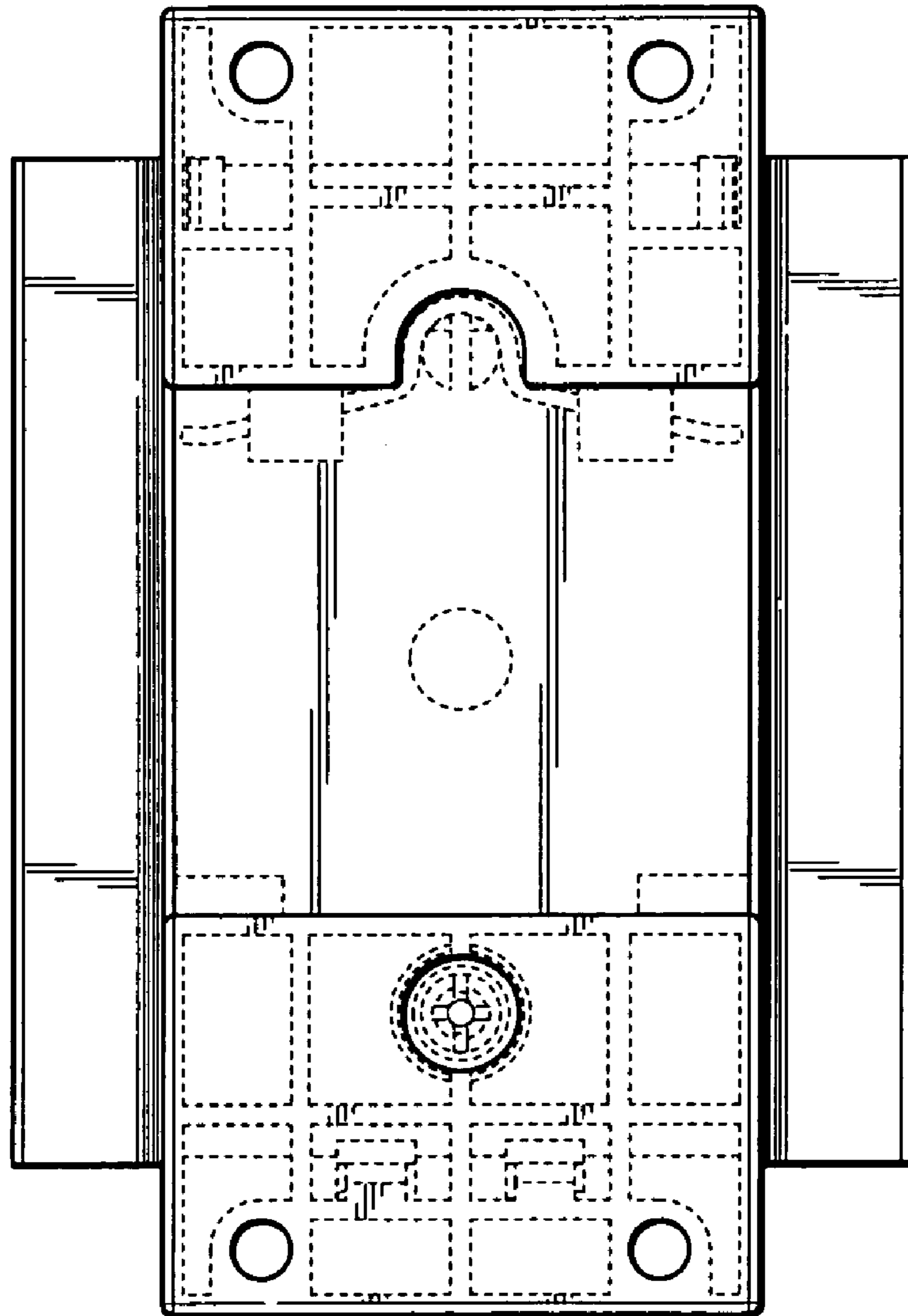


FIG 3

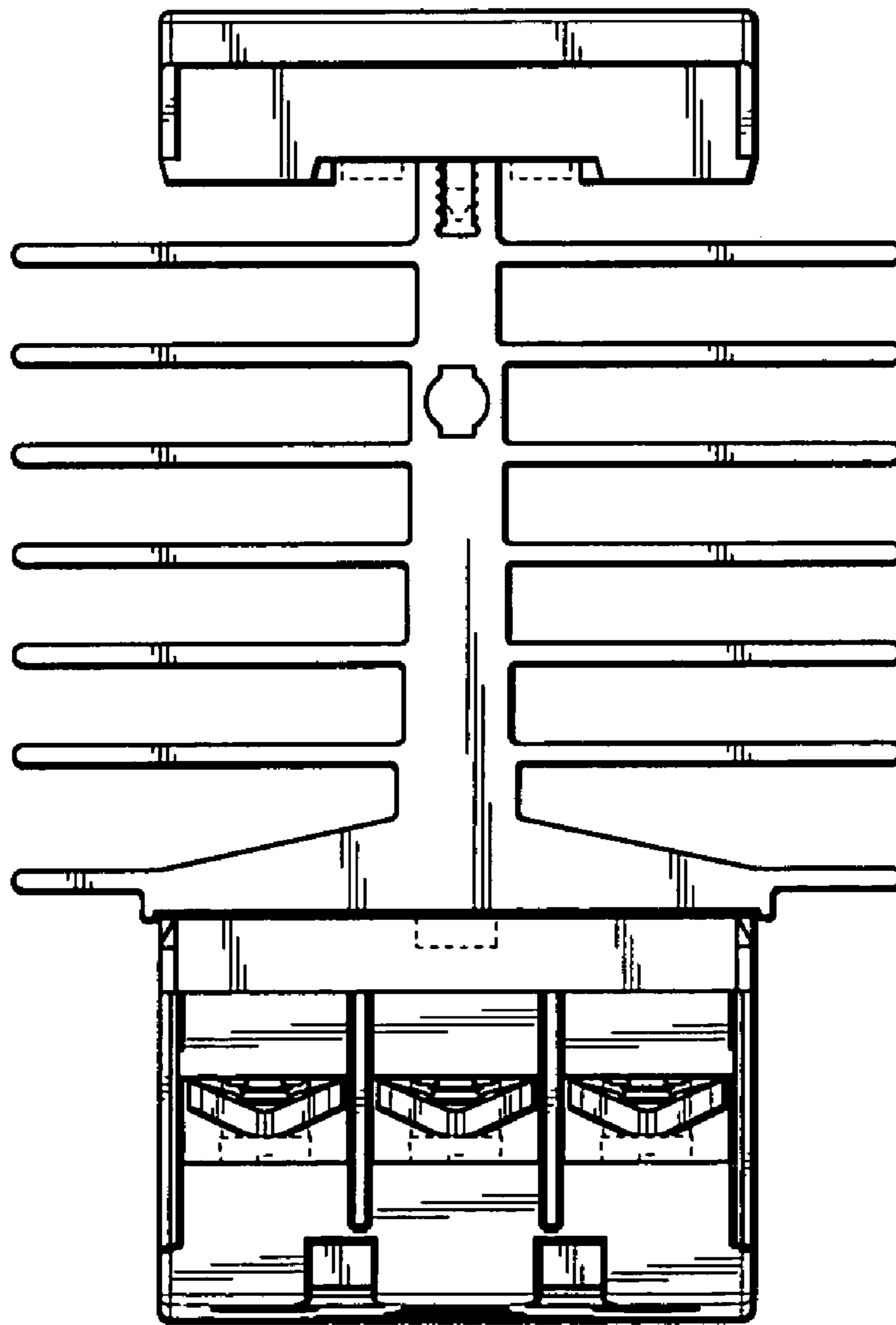




FIG 4

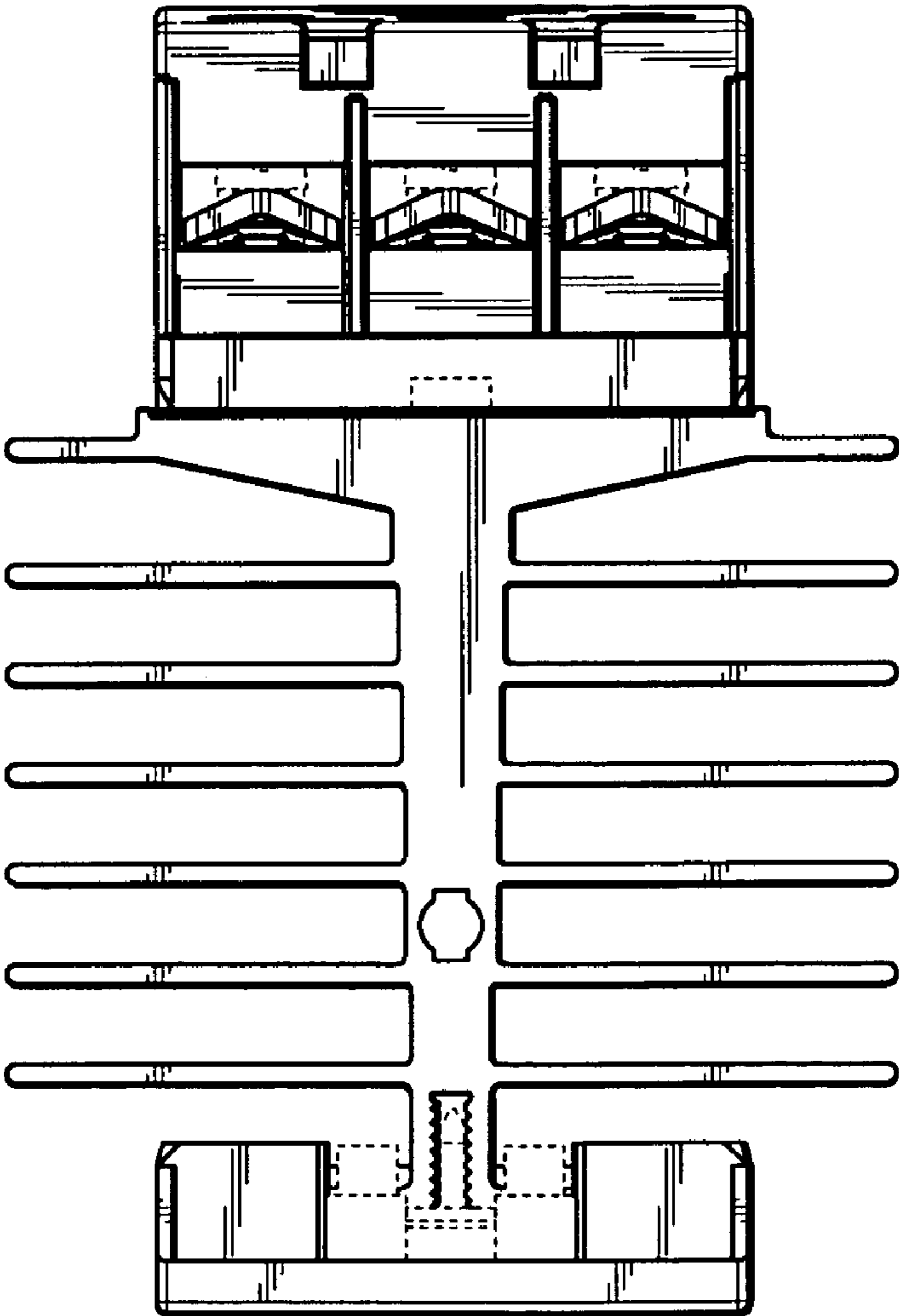


FIG 5

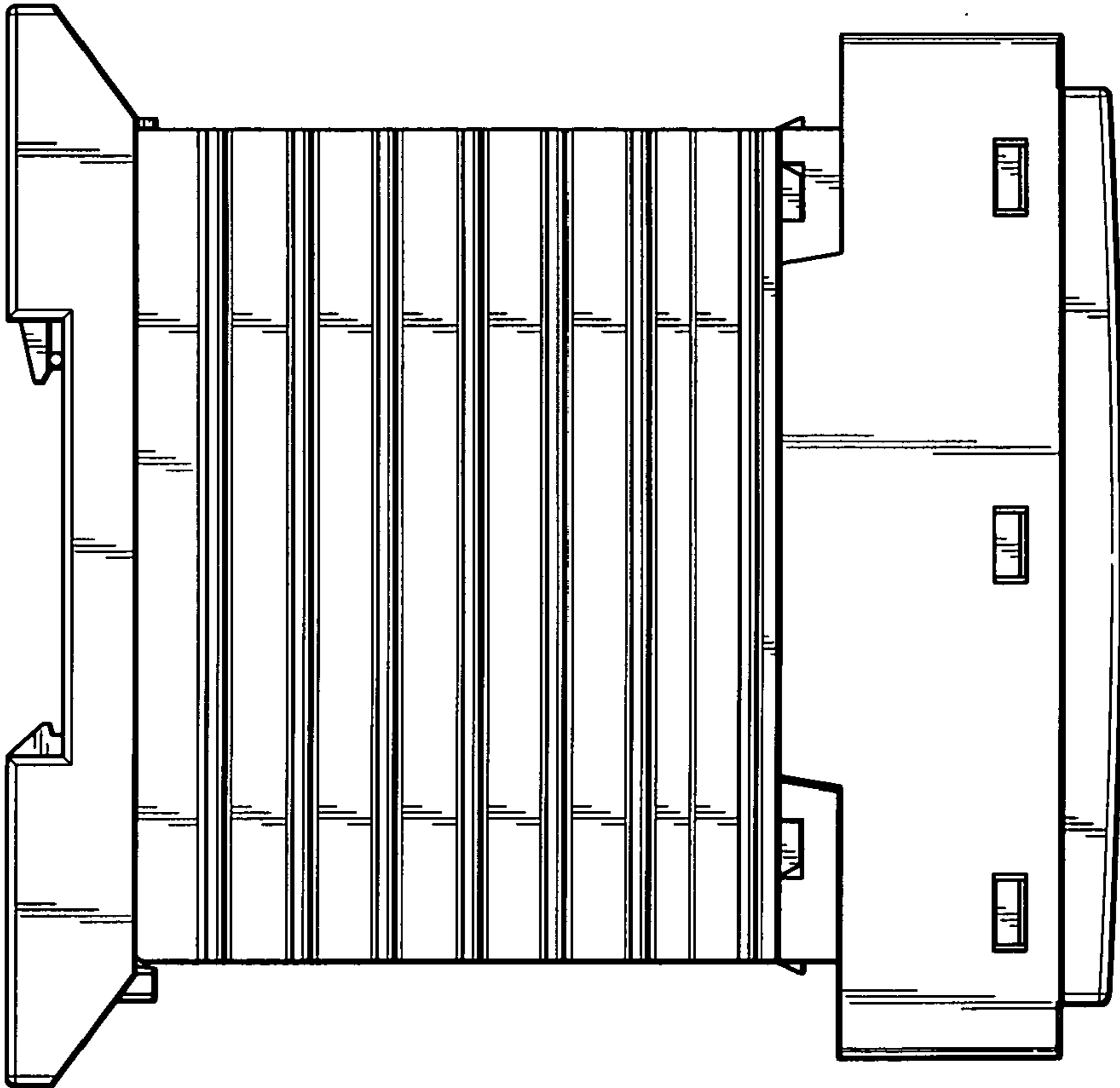


FIG 6

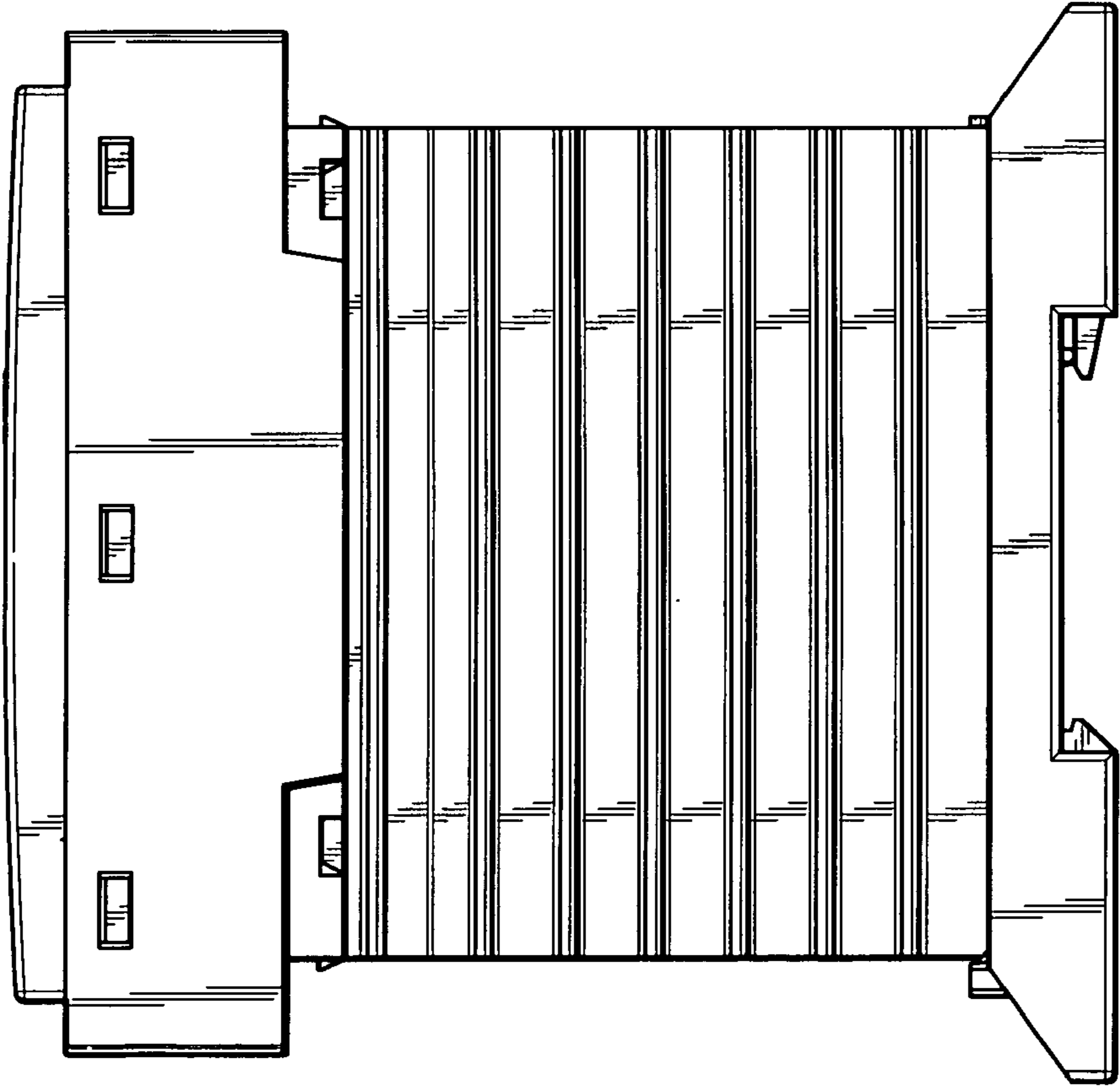




FIG 7

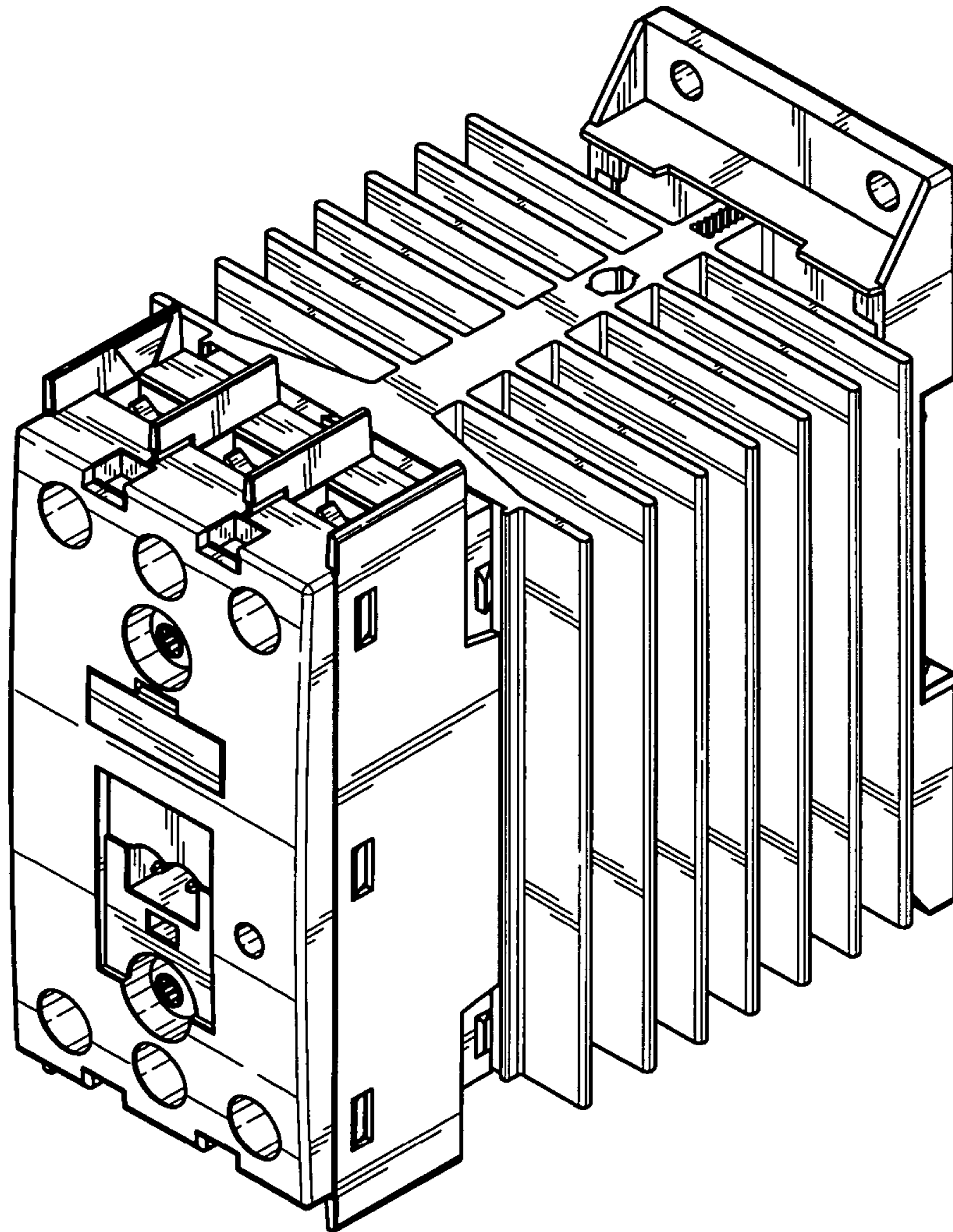


FIG 8

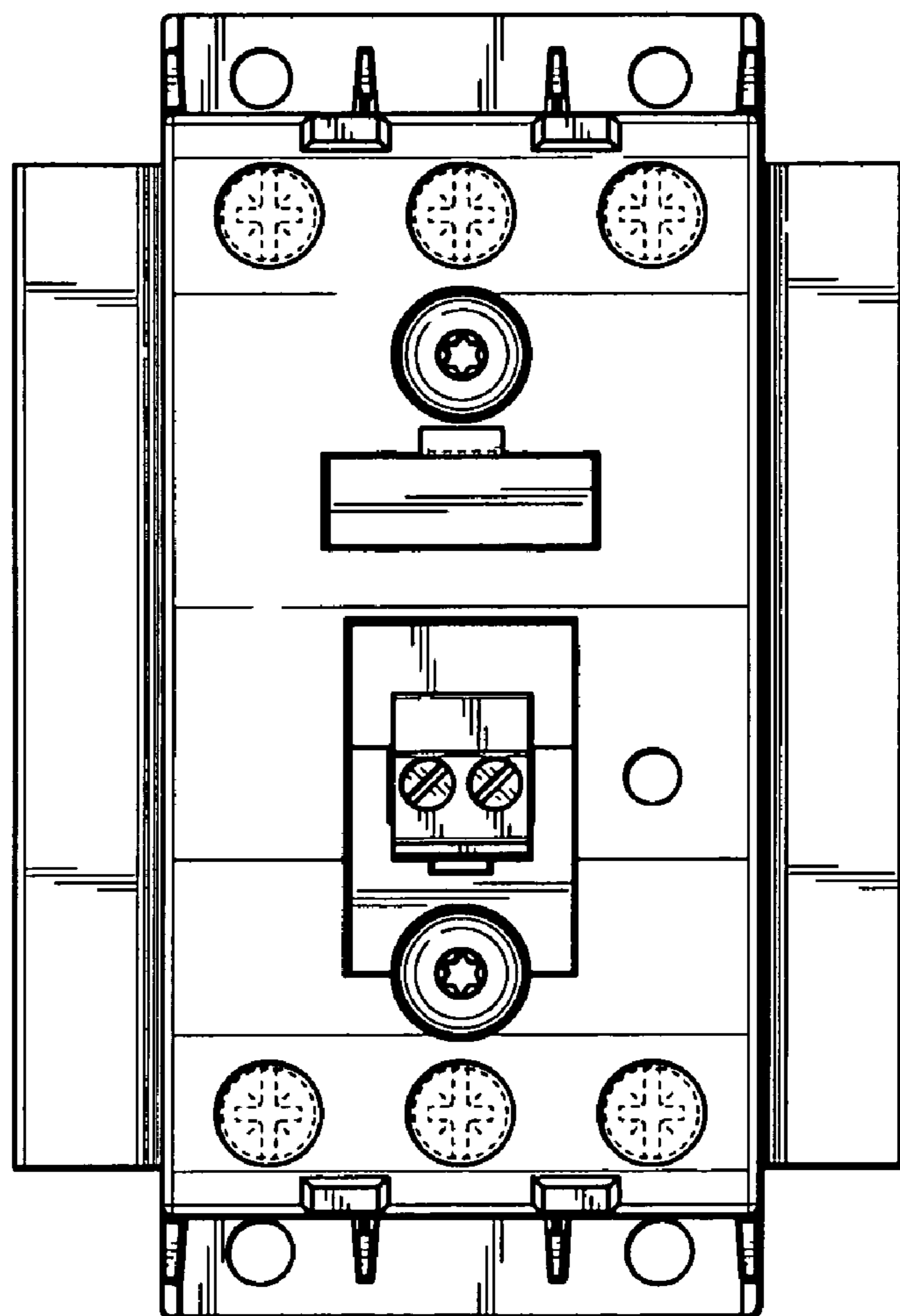


FIG 9

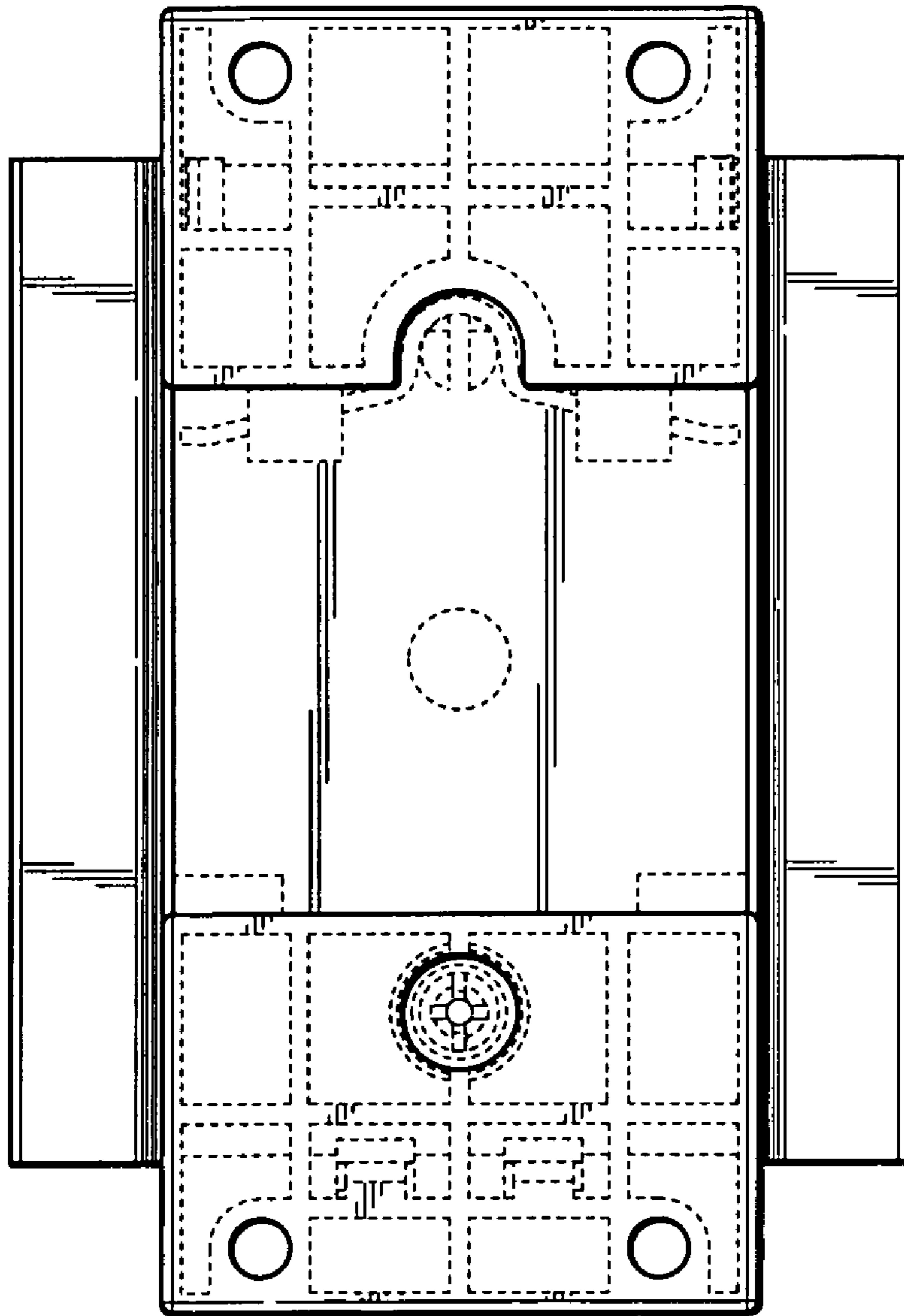


FIG 10

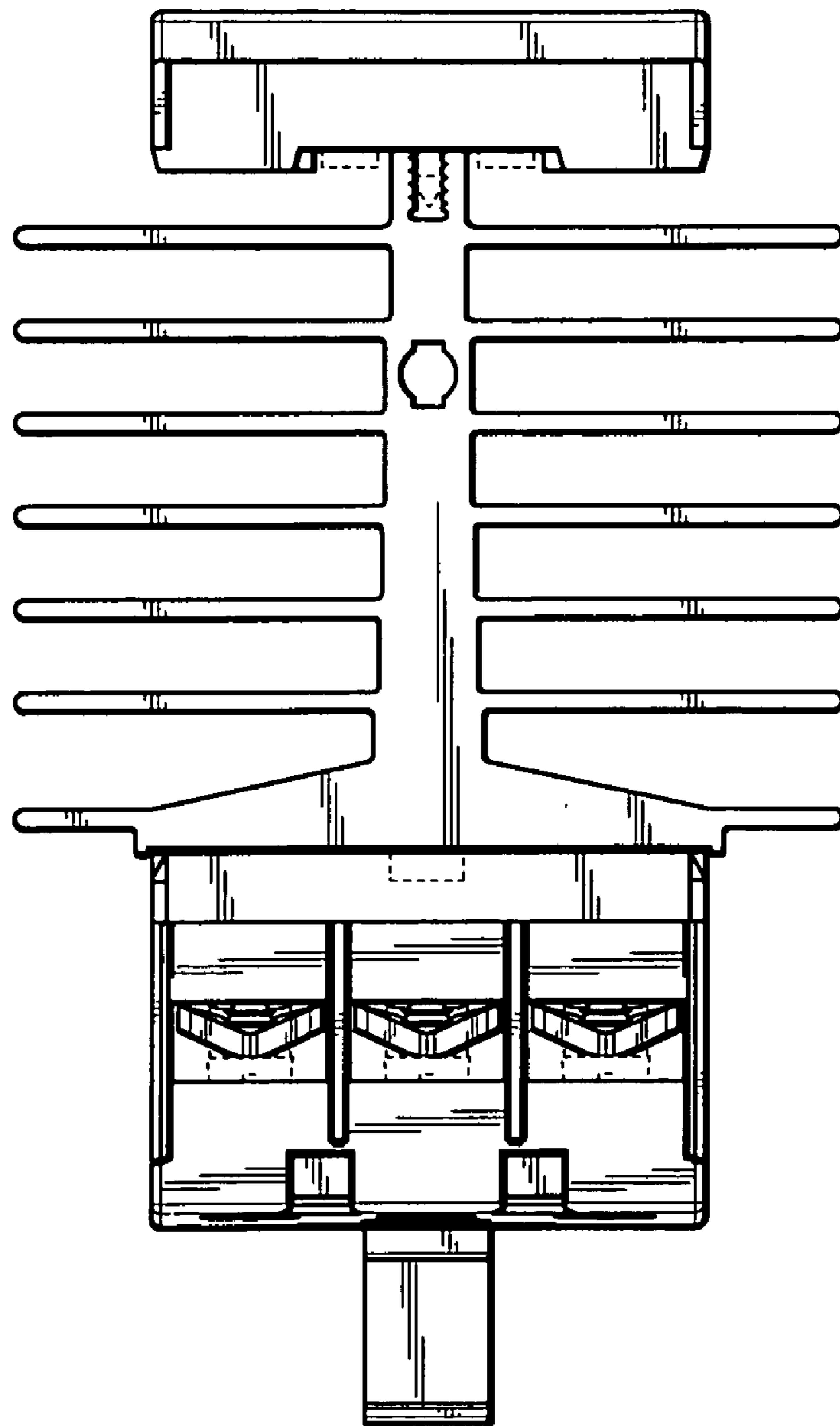


FIG 11

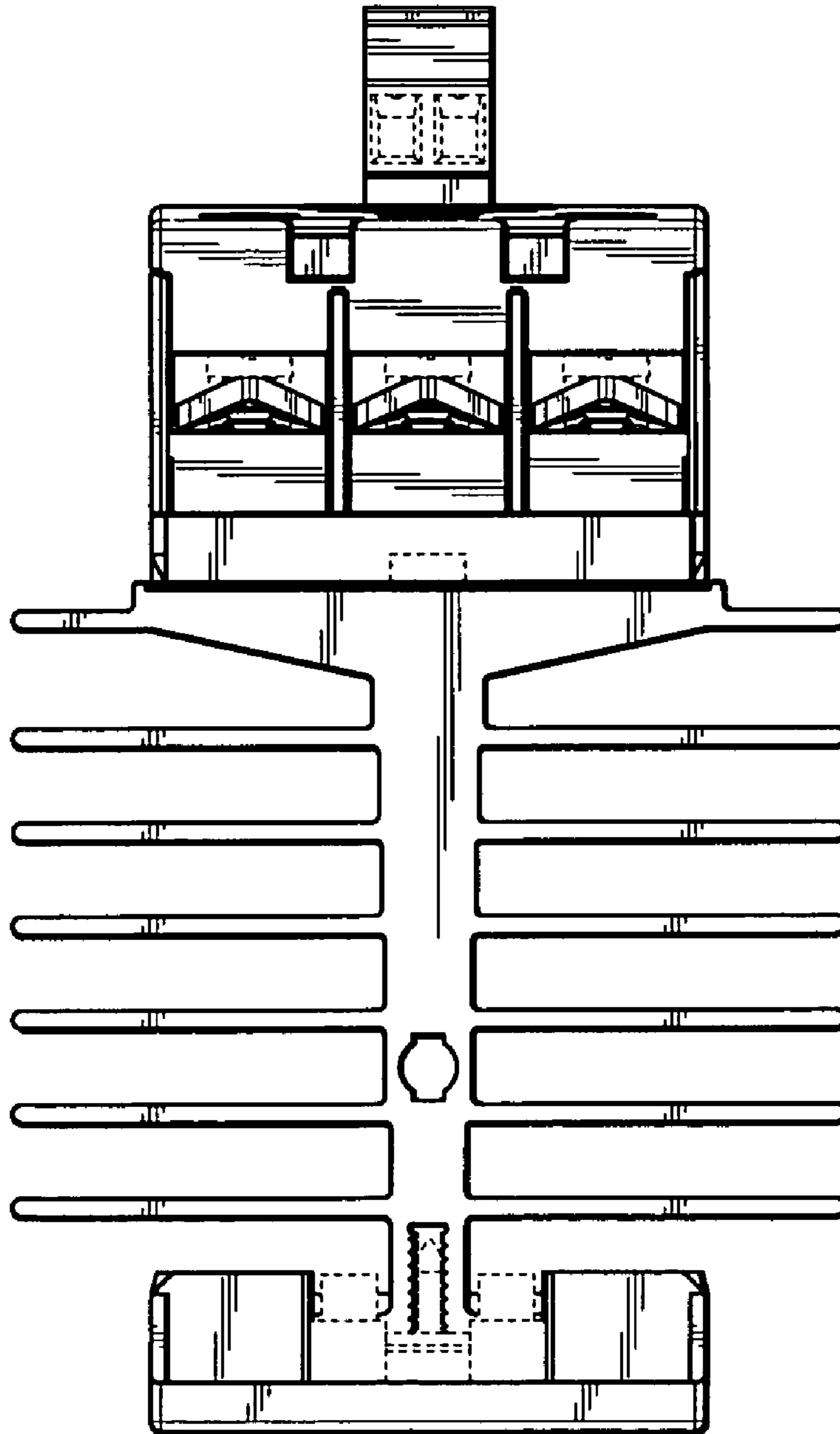


FIG 12

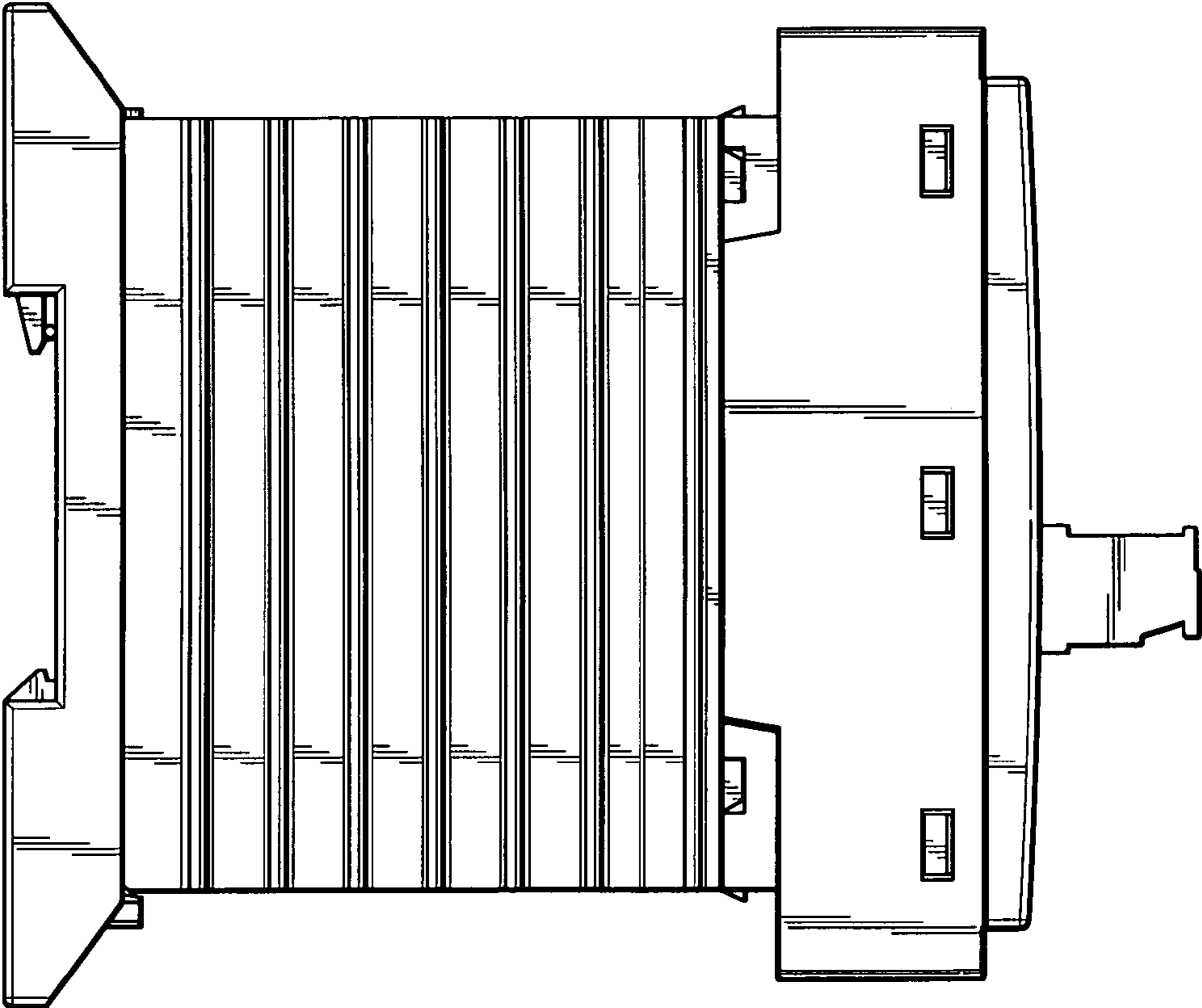




FIG 13

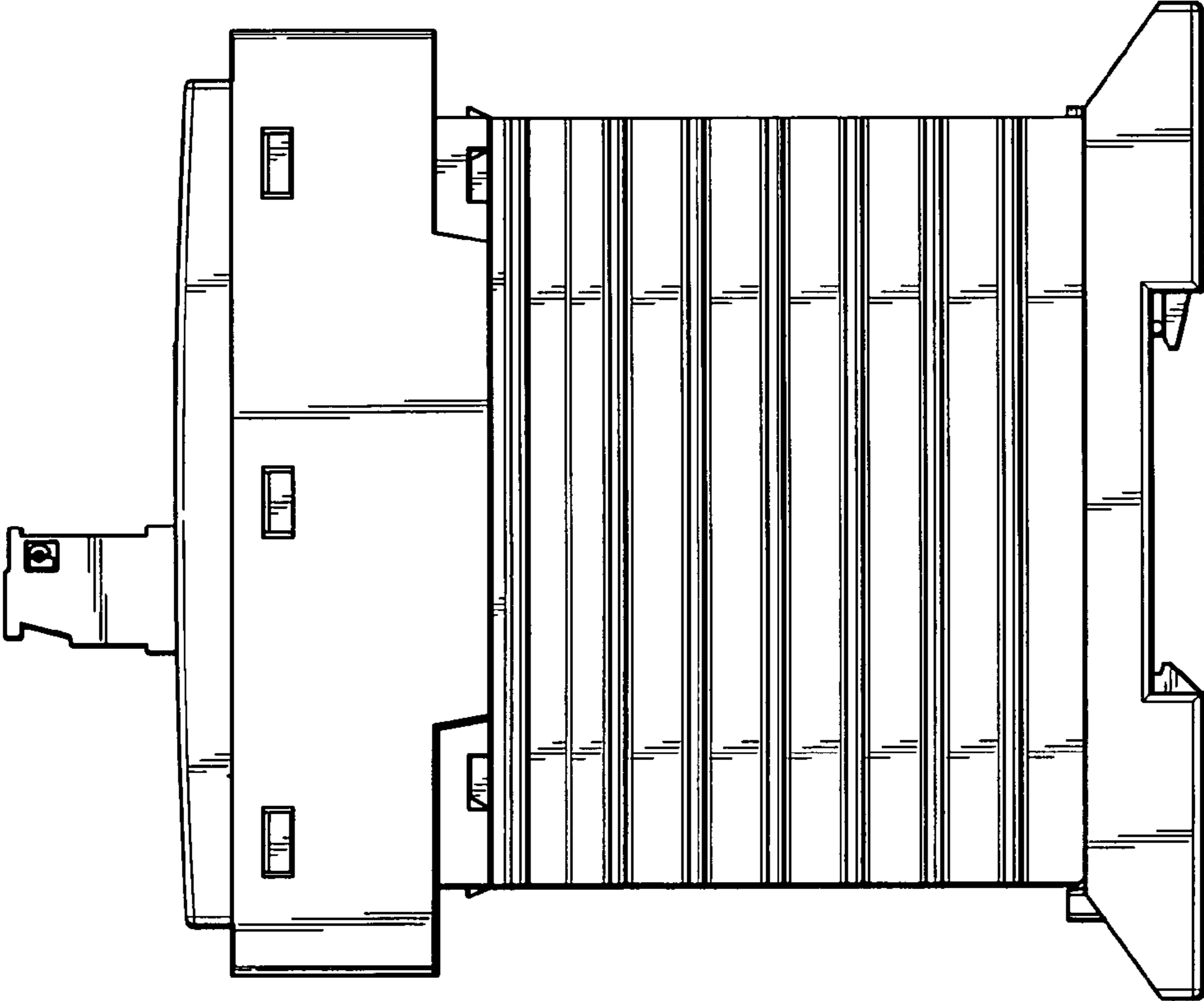


FIG 14

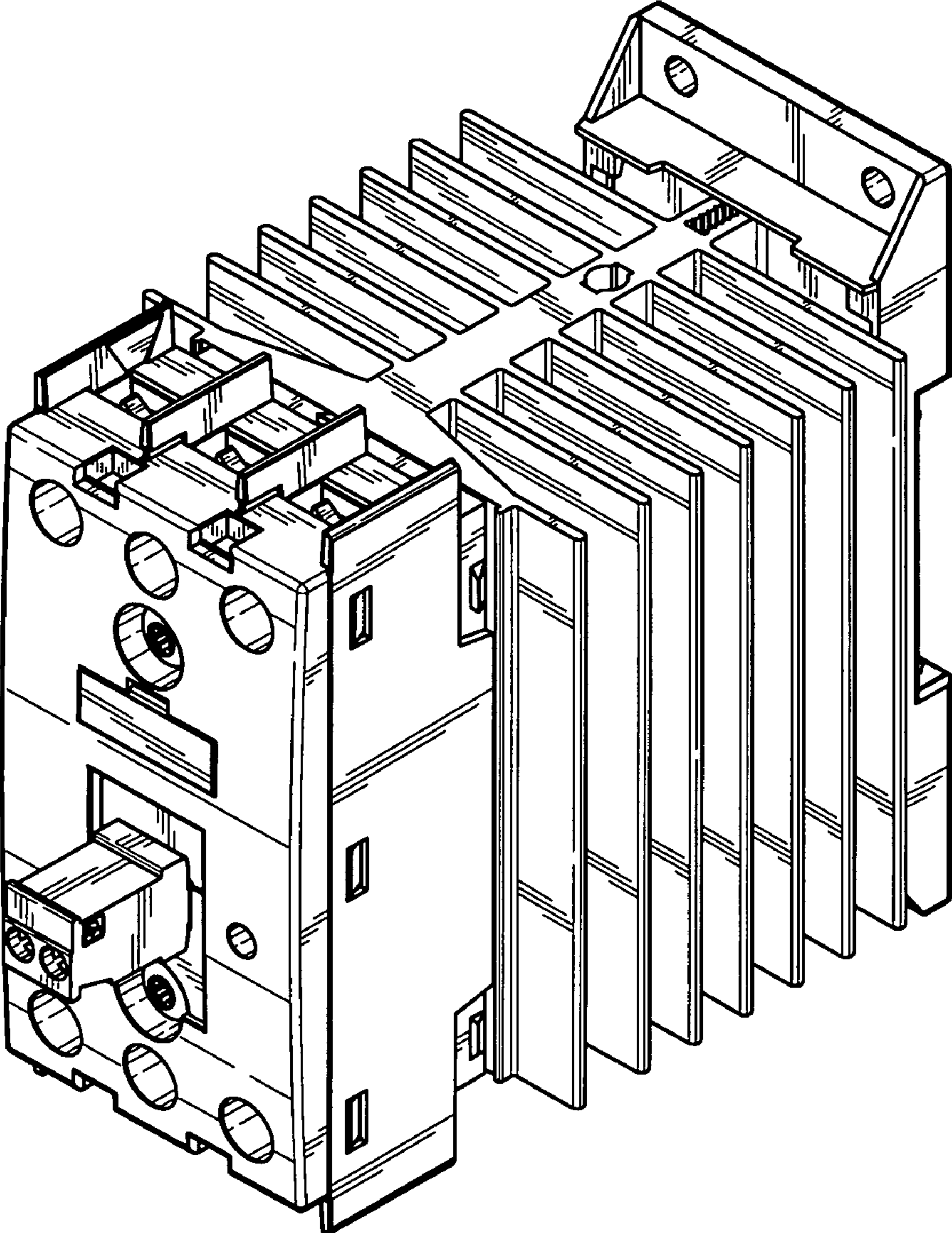


FIG 15

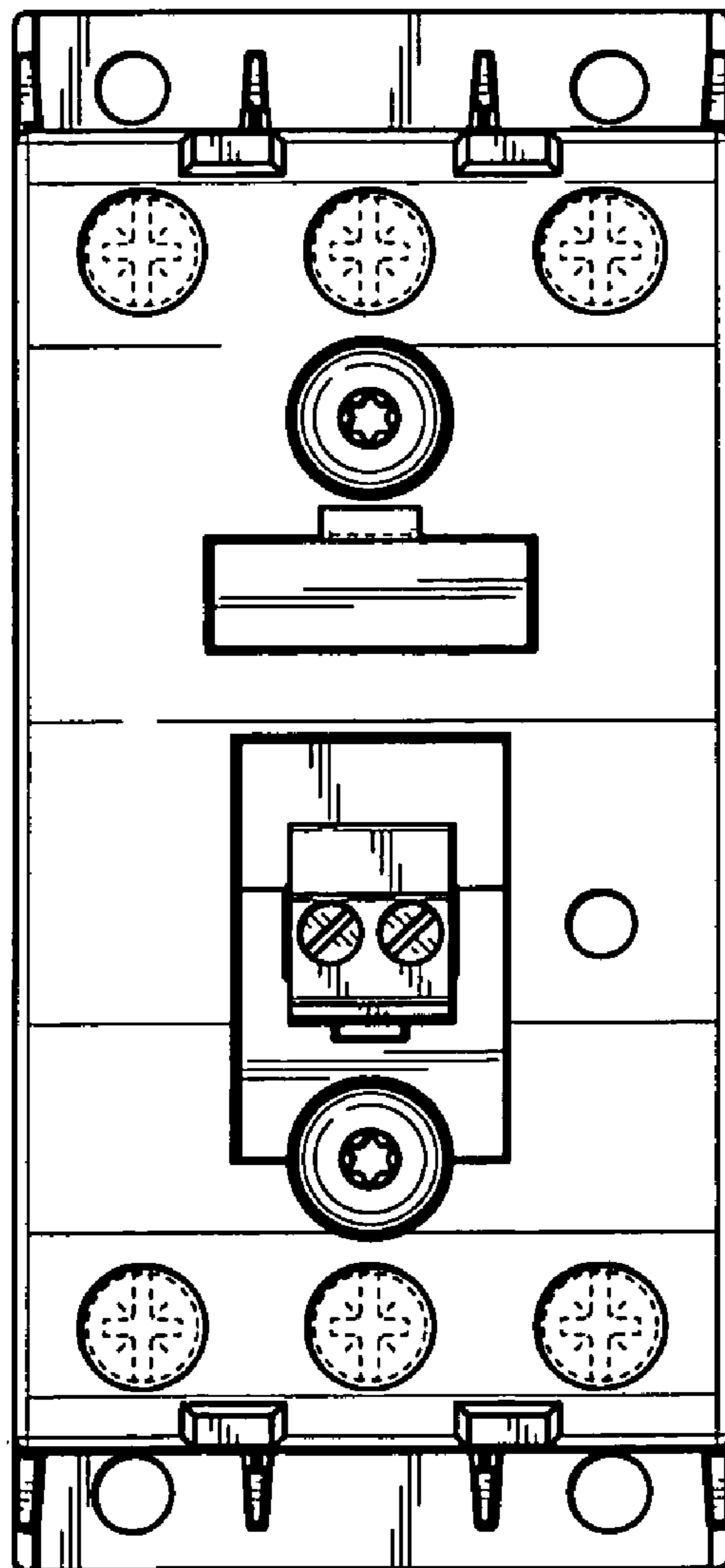


FIG 16

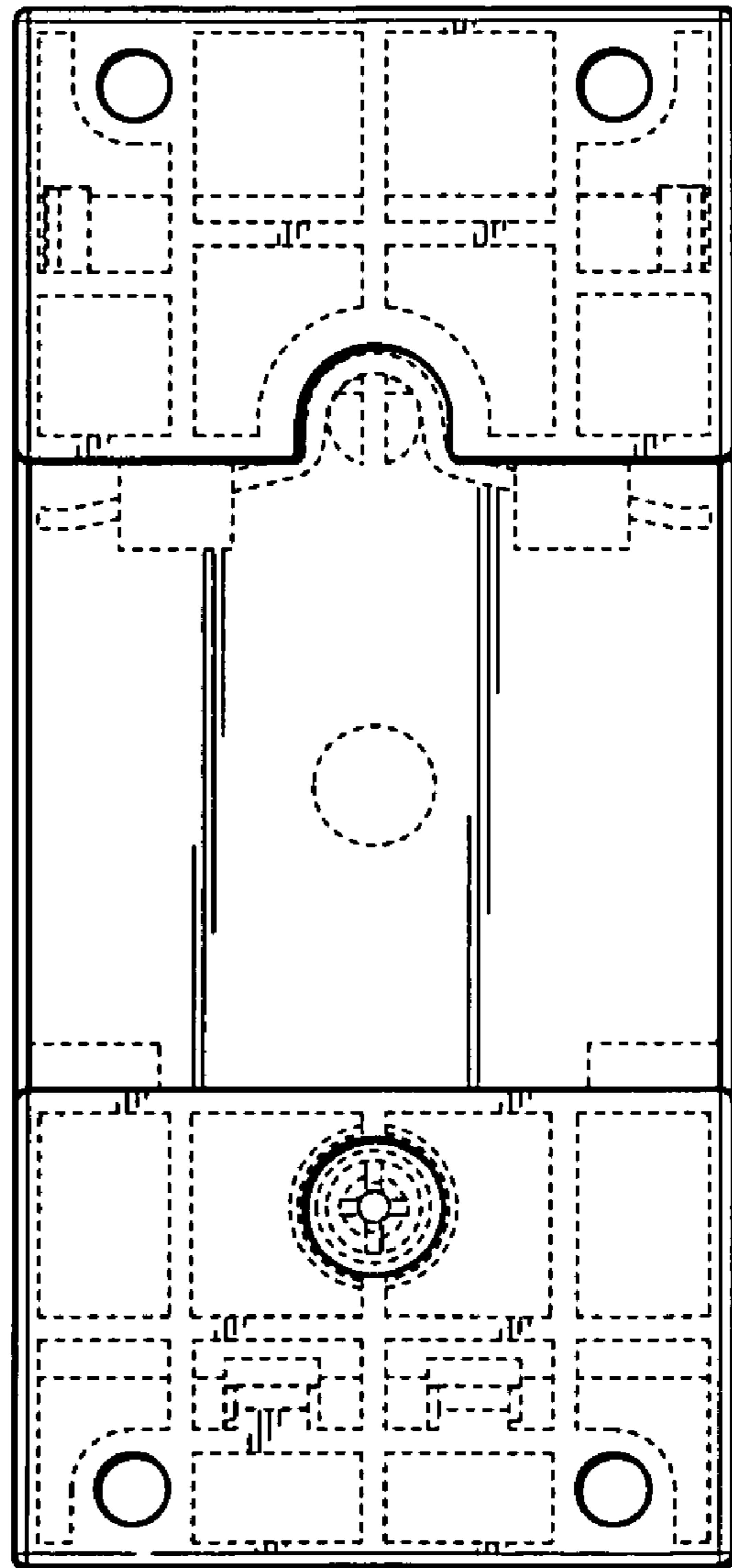


FIG 17

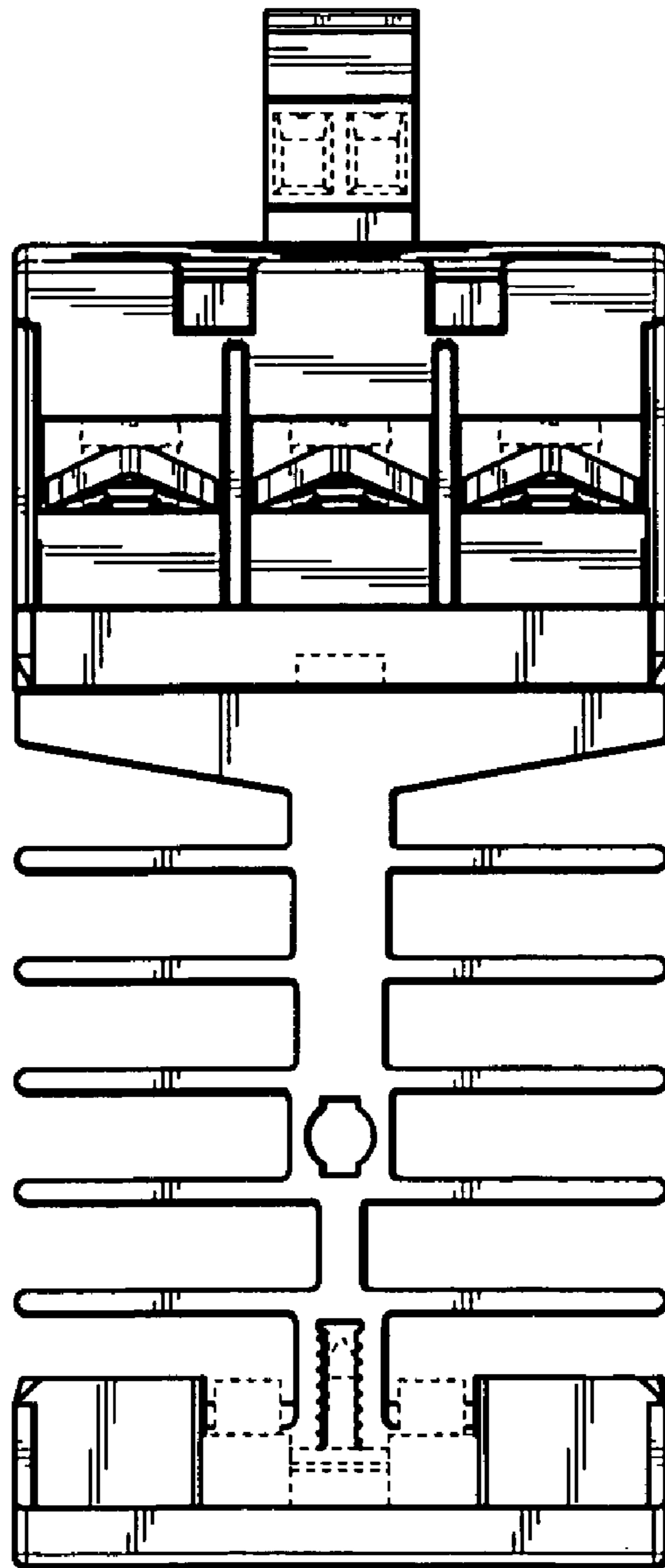


FIG 18

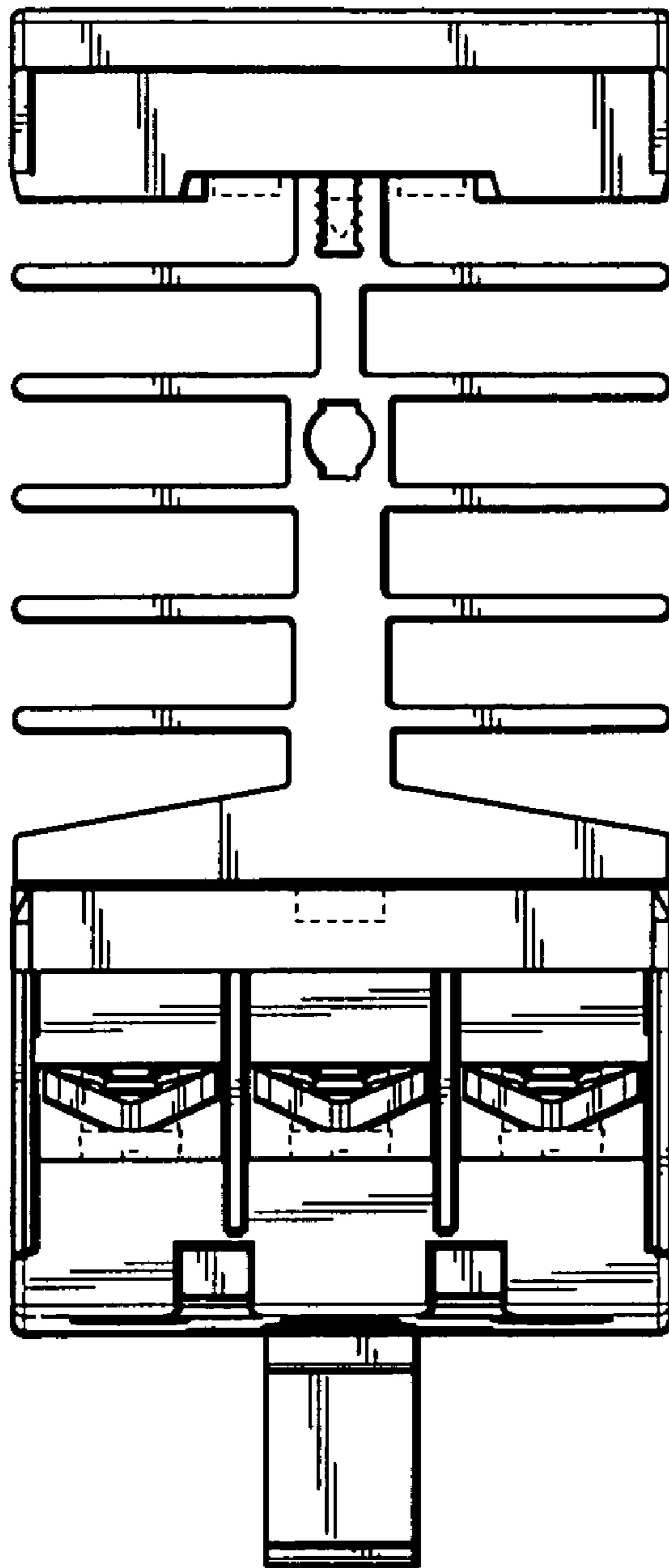




FIG 19

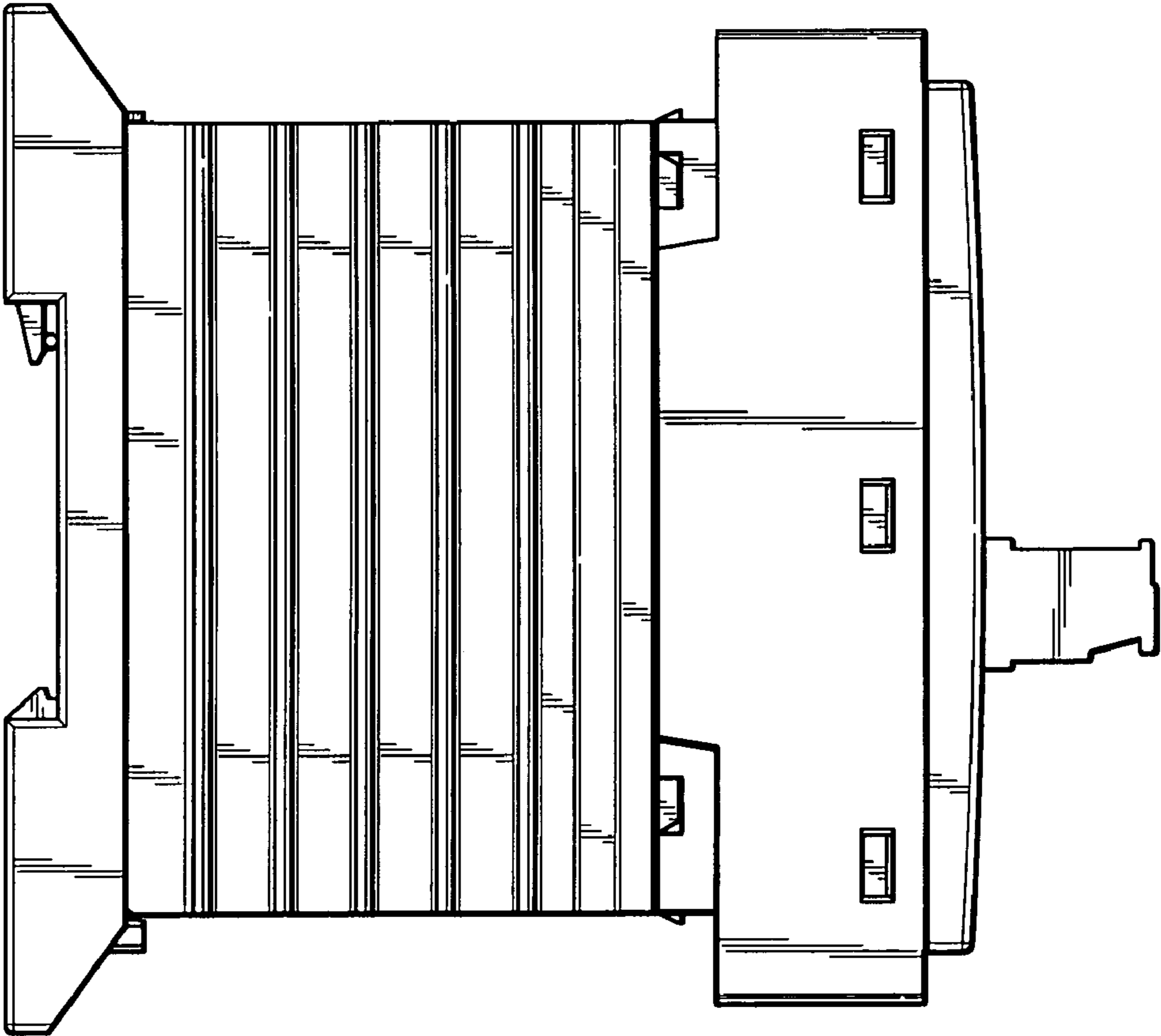


FIG 20

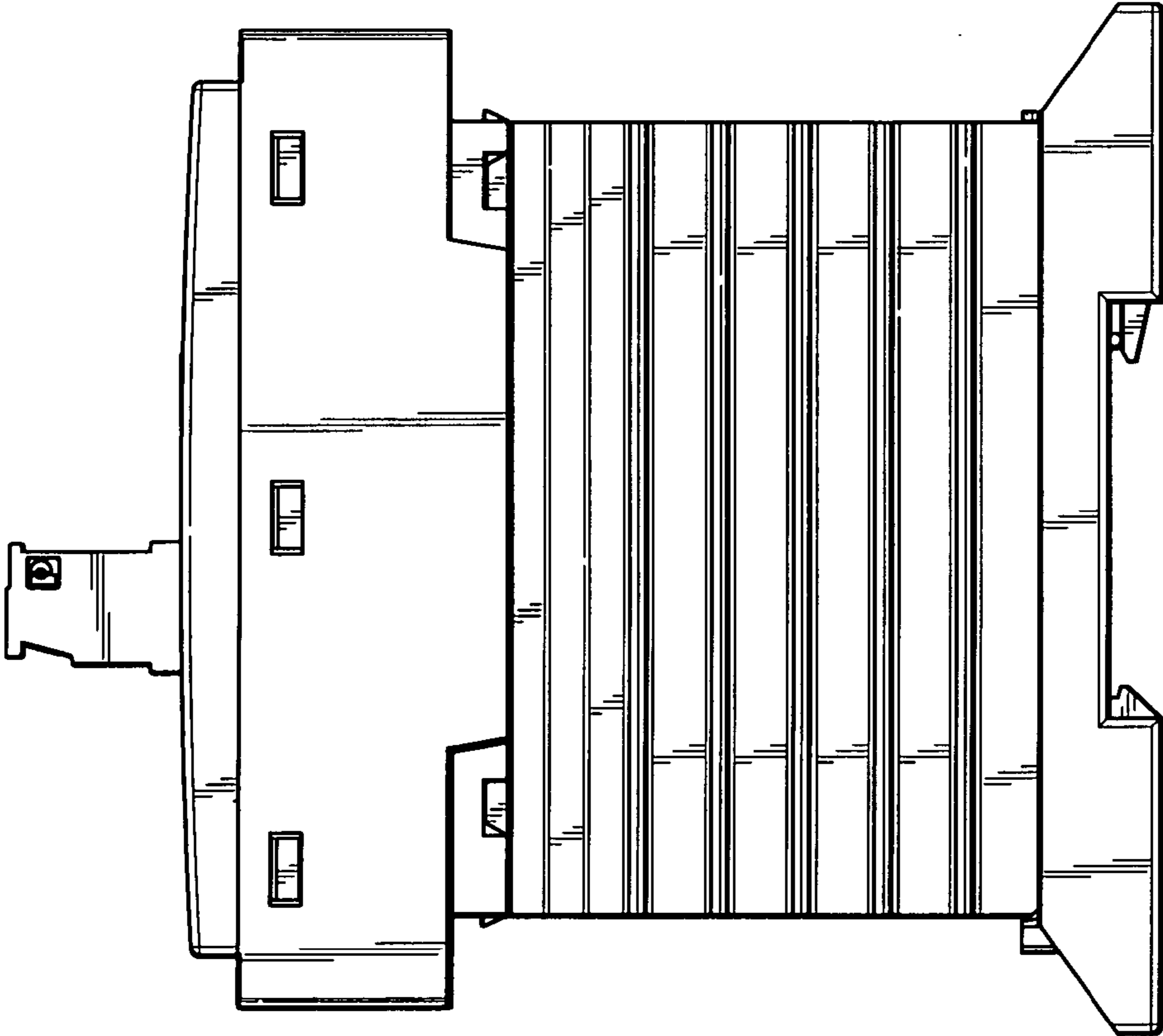


FIG 21

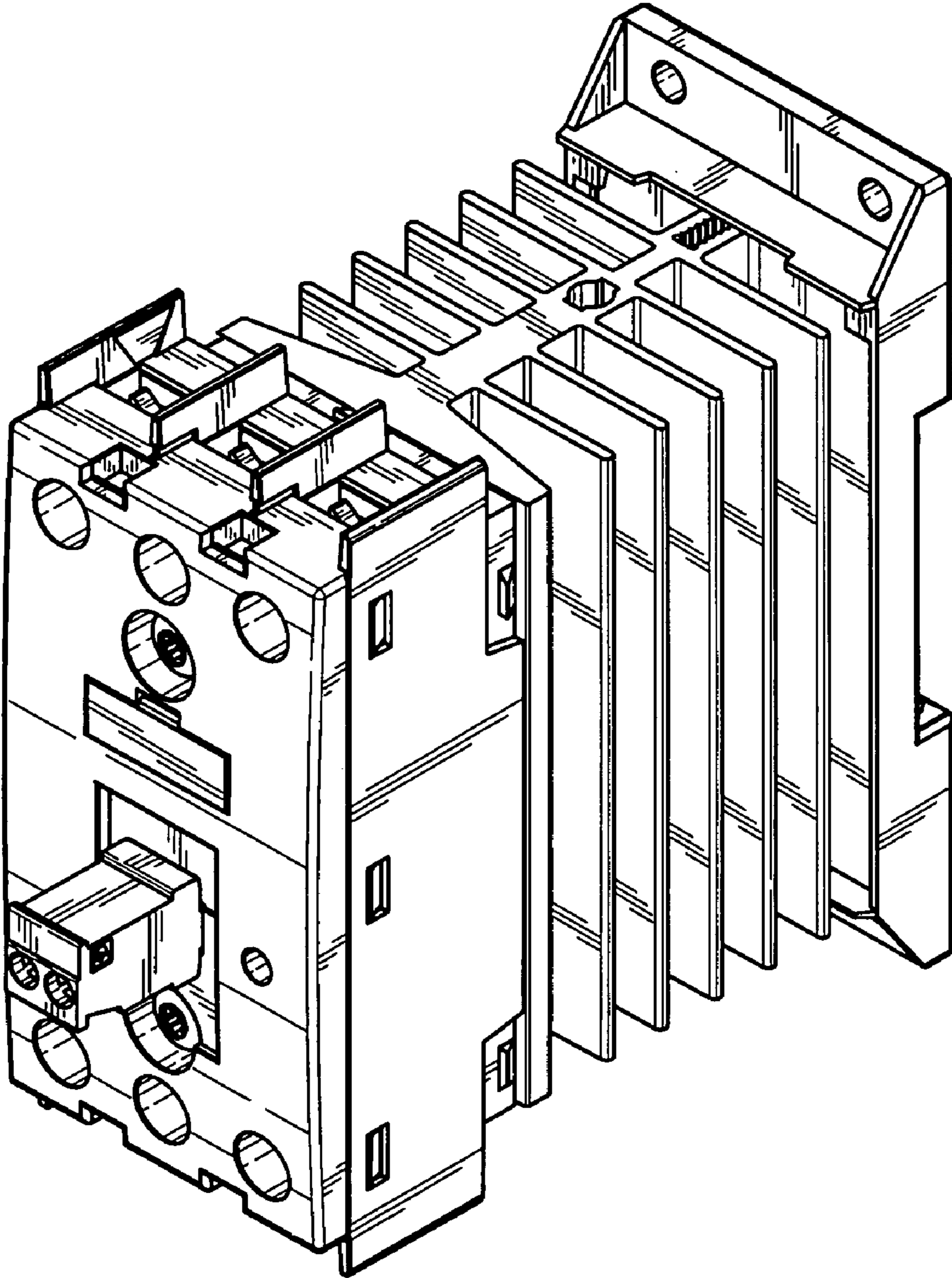


FIG 22

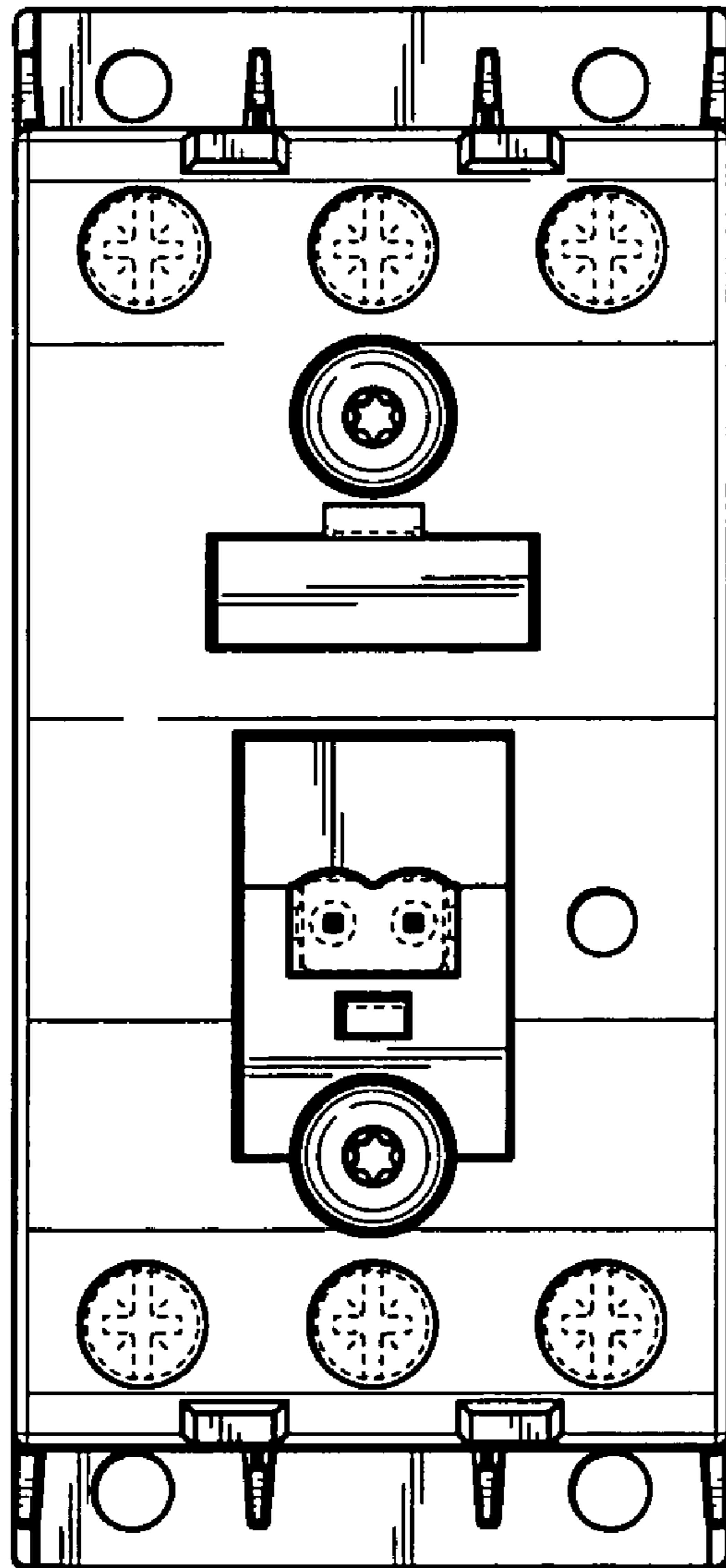


FIG 23

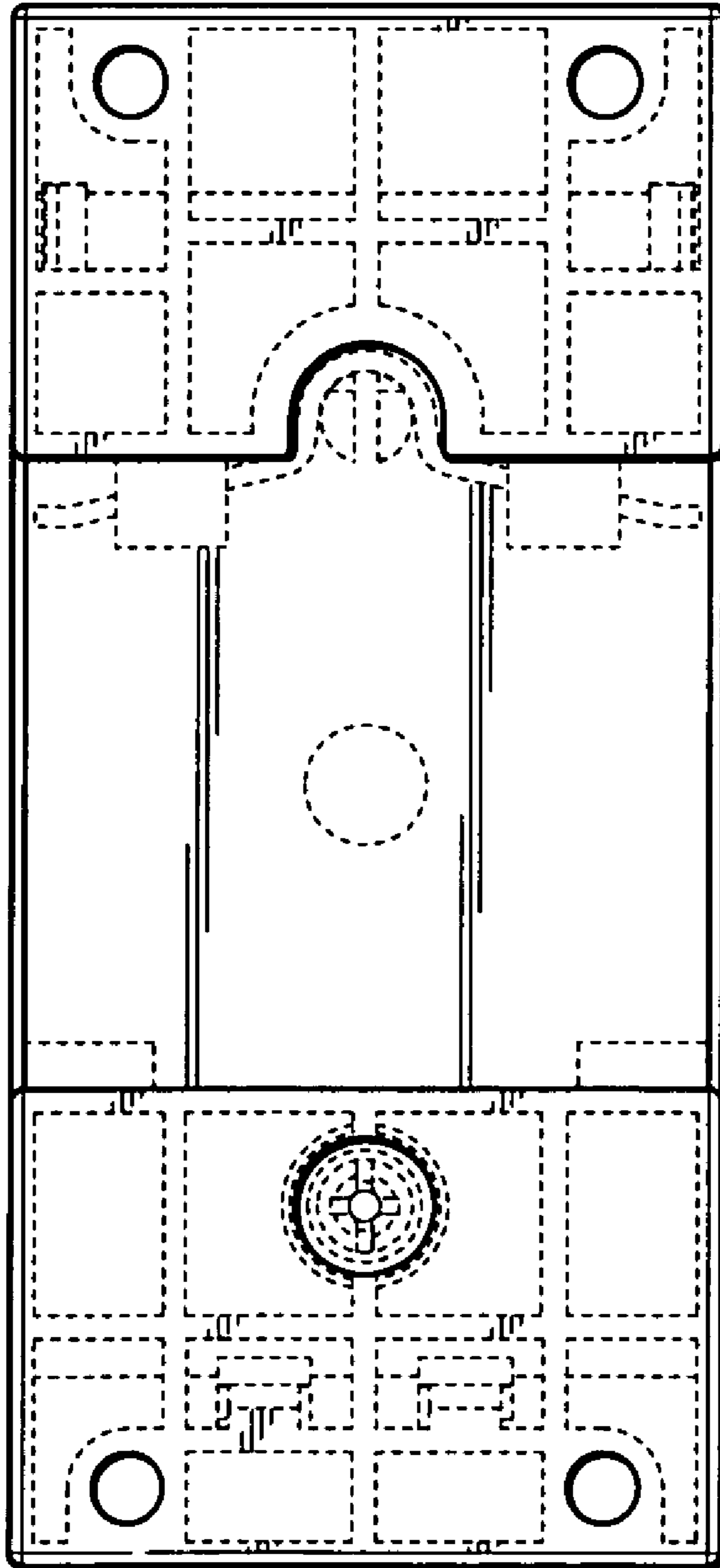


FIG 24

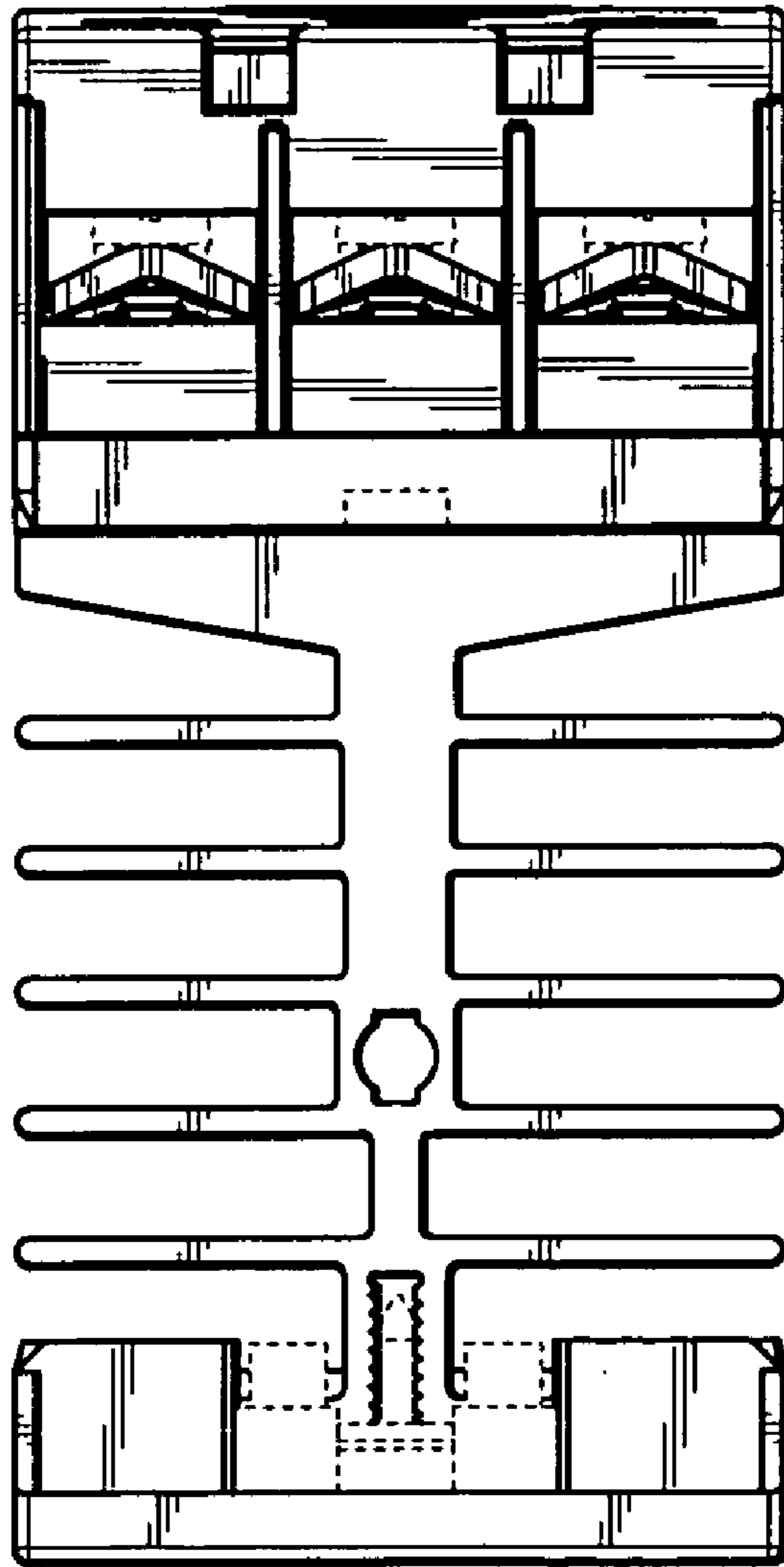




FIG 25

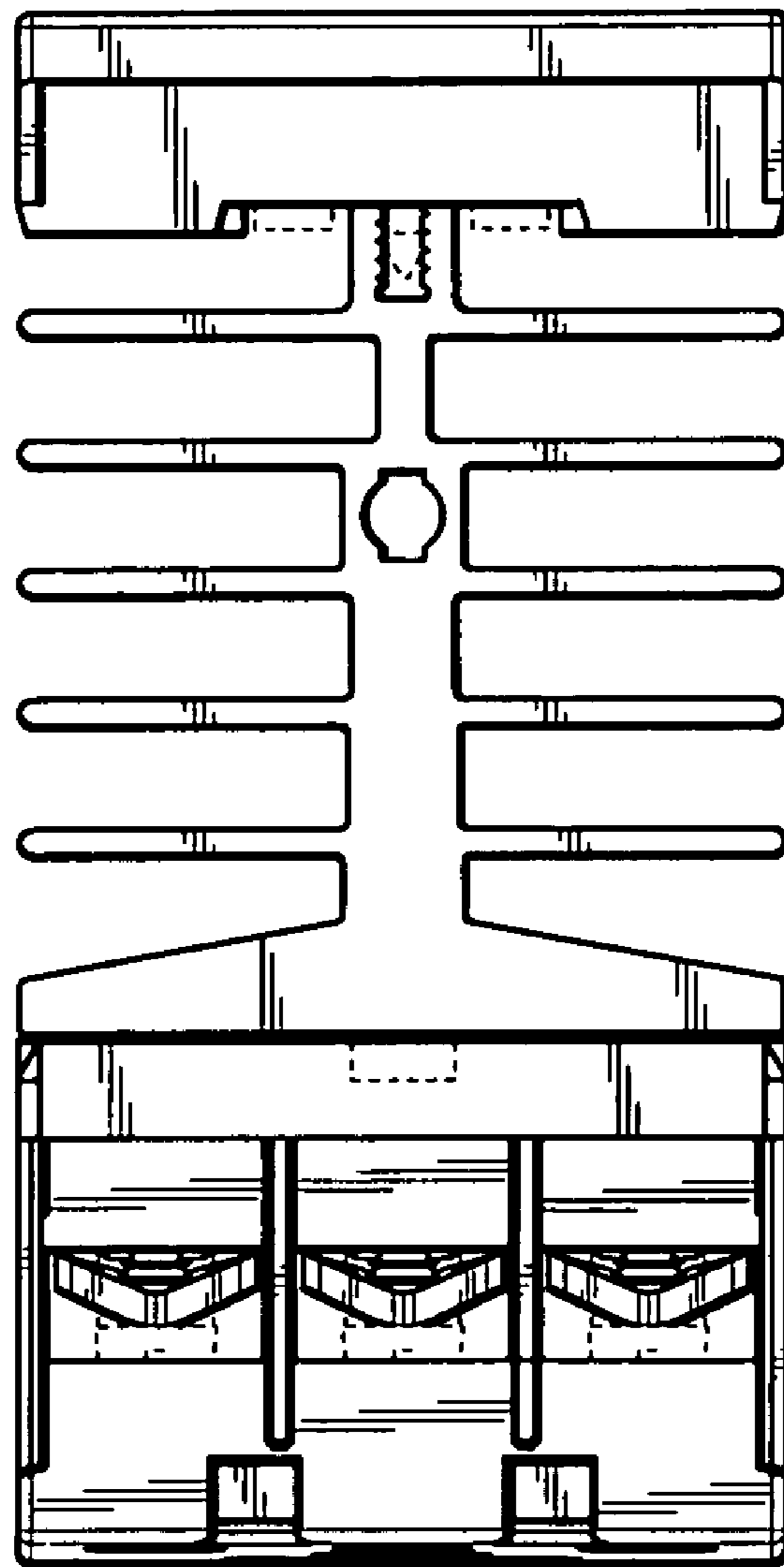


FIG 26

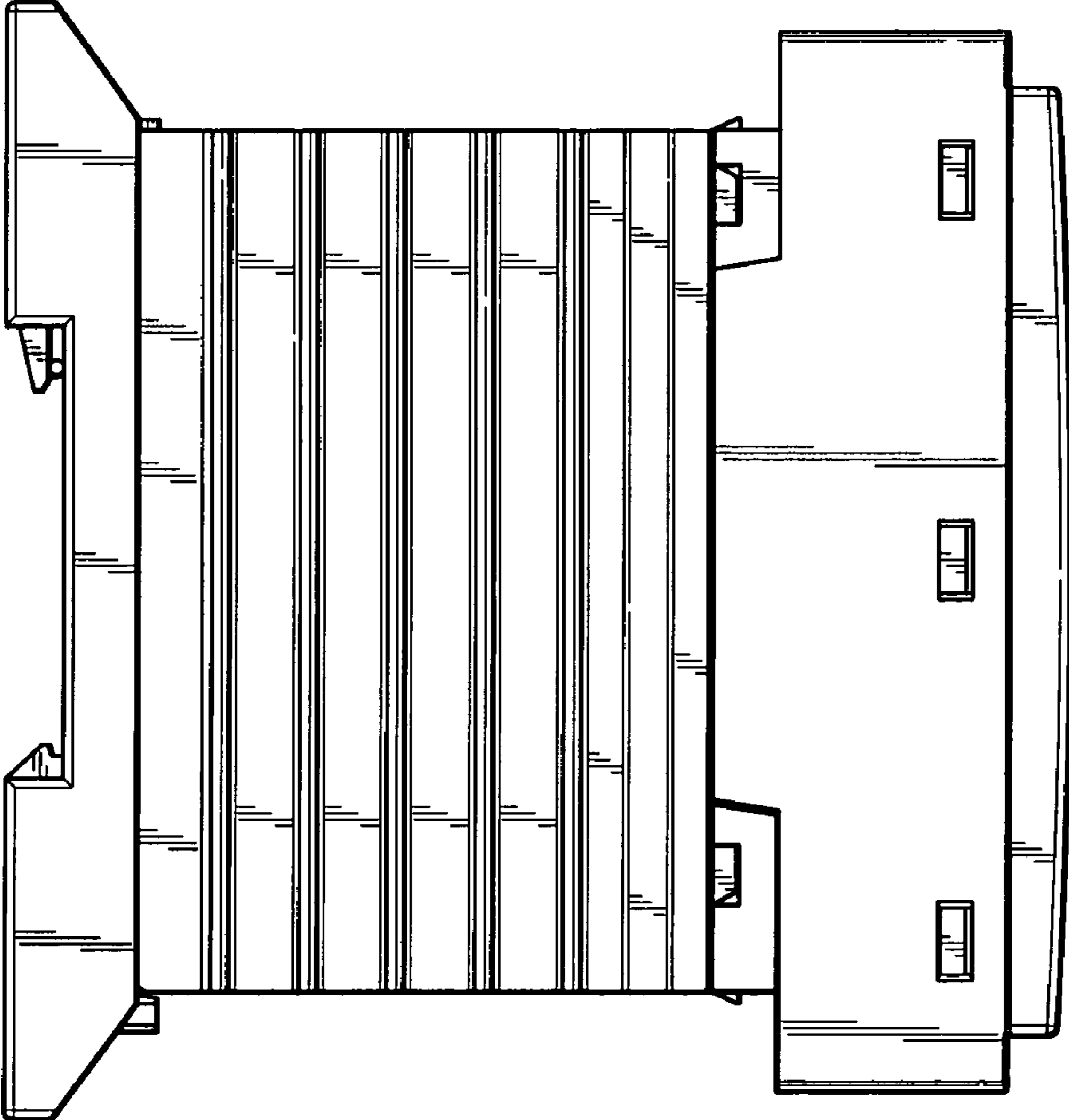


FIG 27

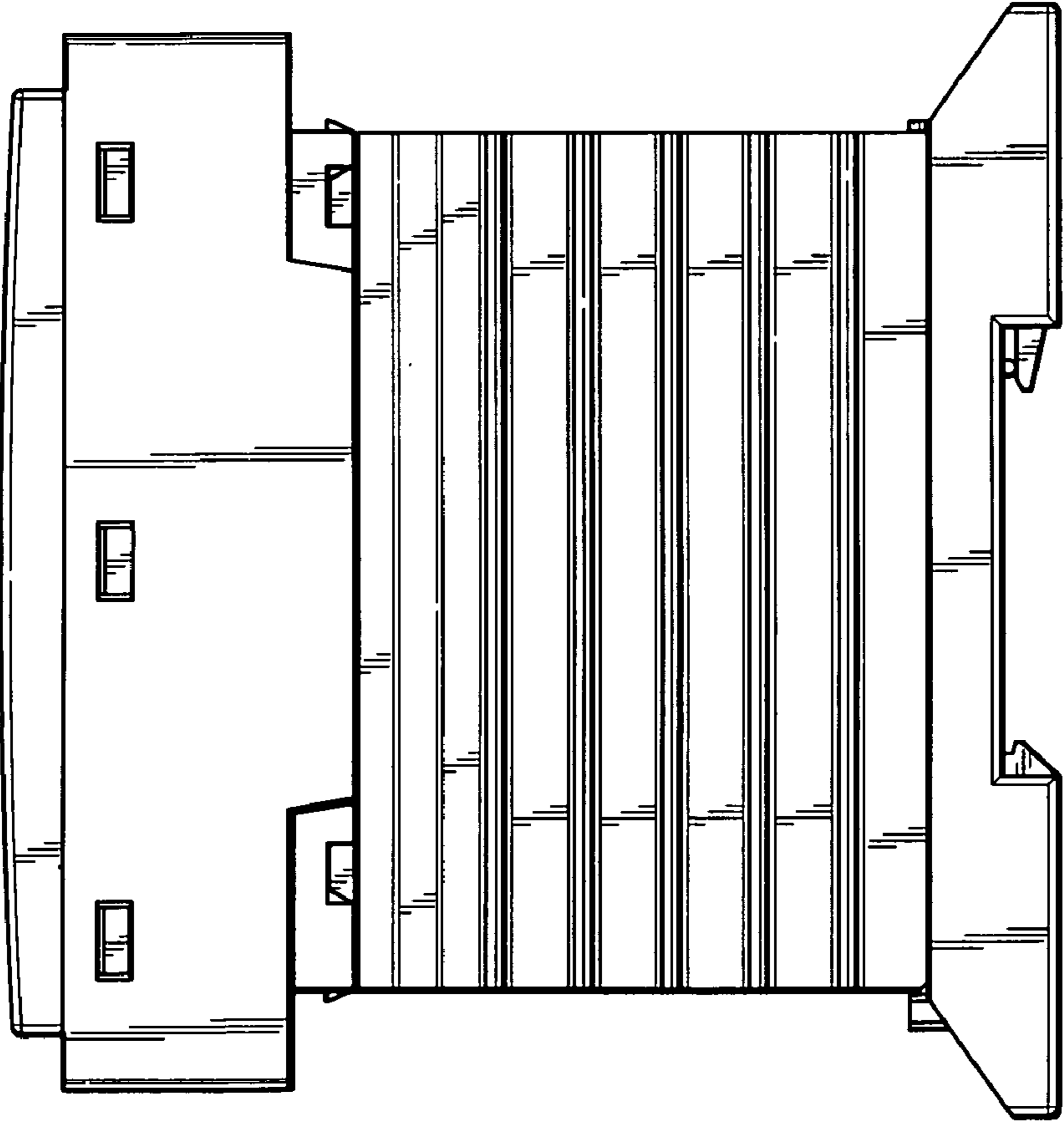


FIG 28

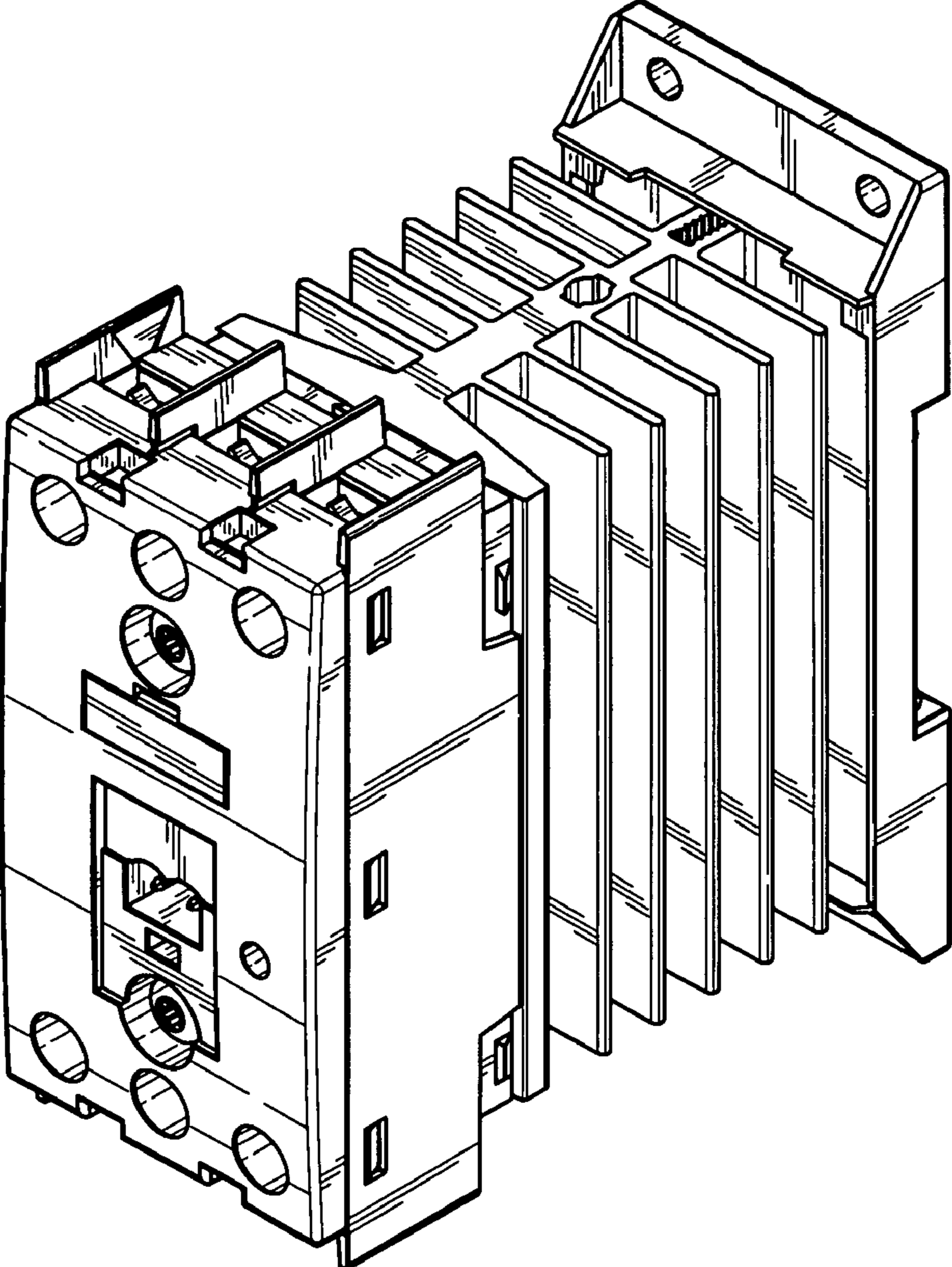


FIG 29

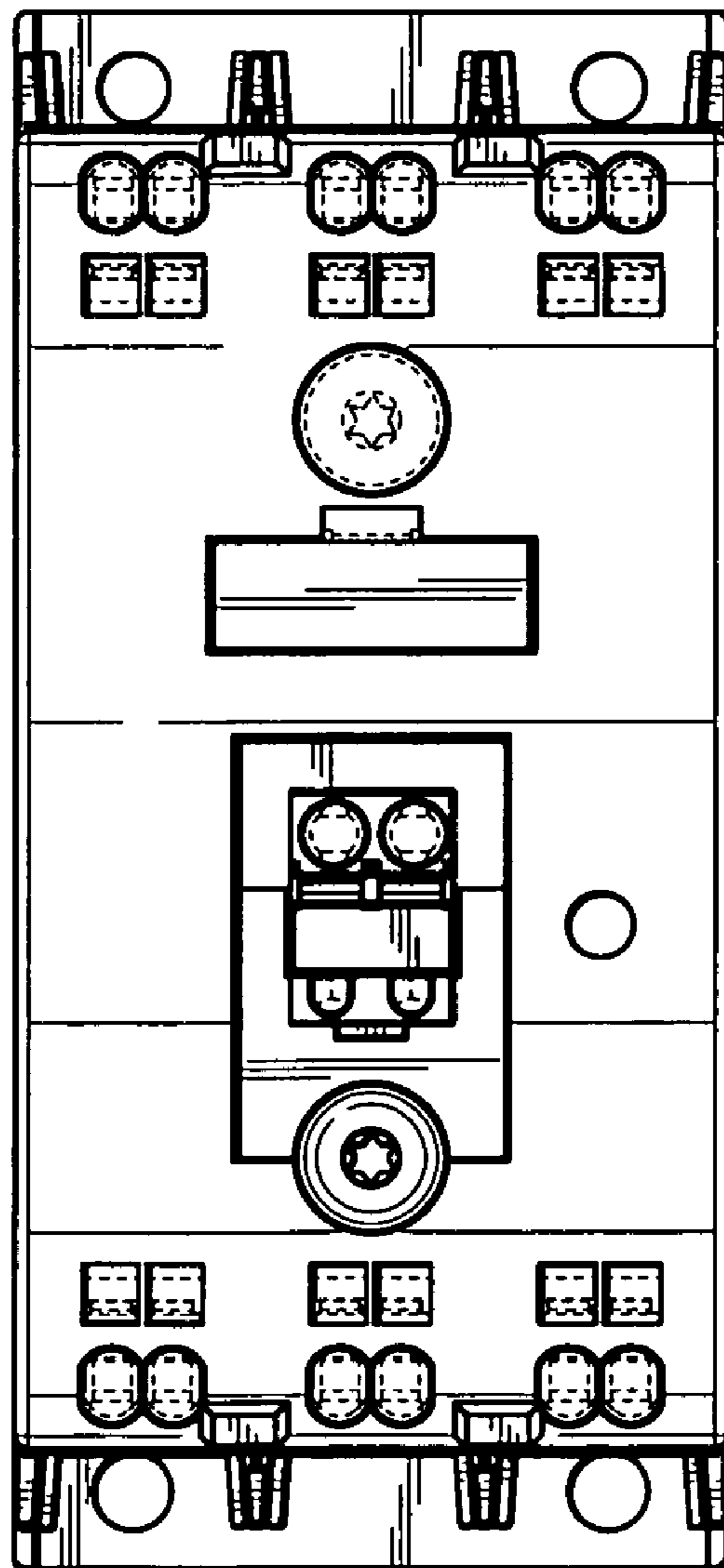


FIG 30

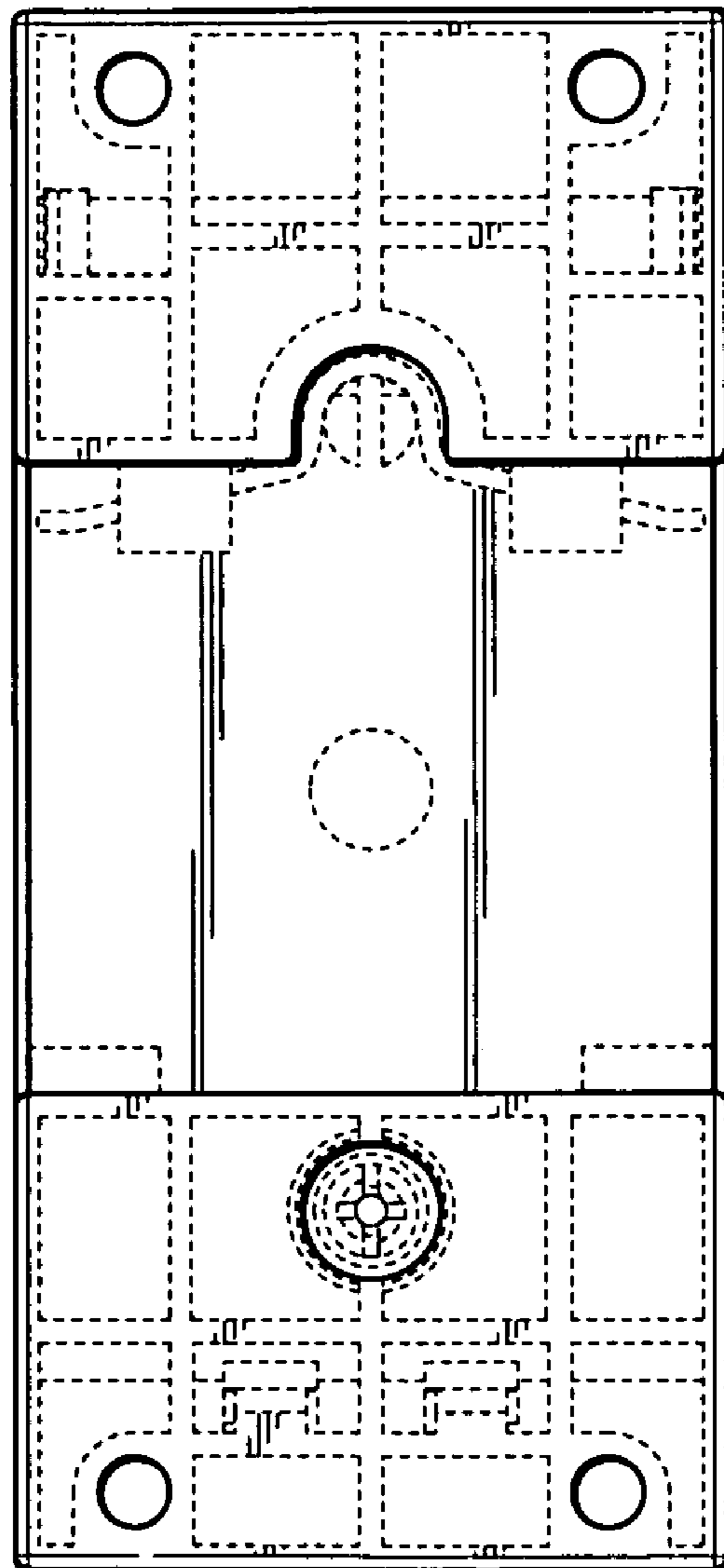




FIG 31

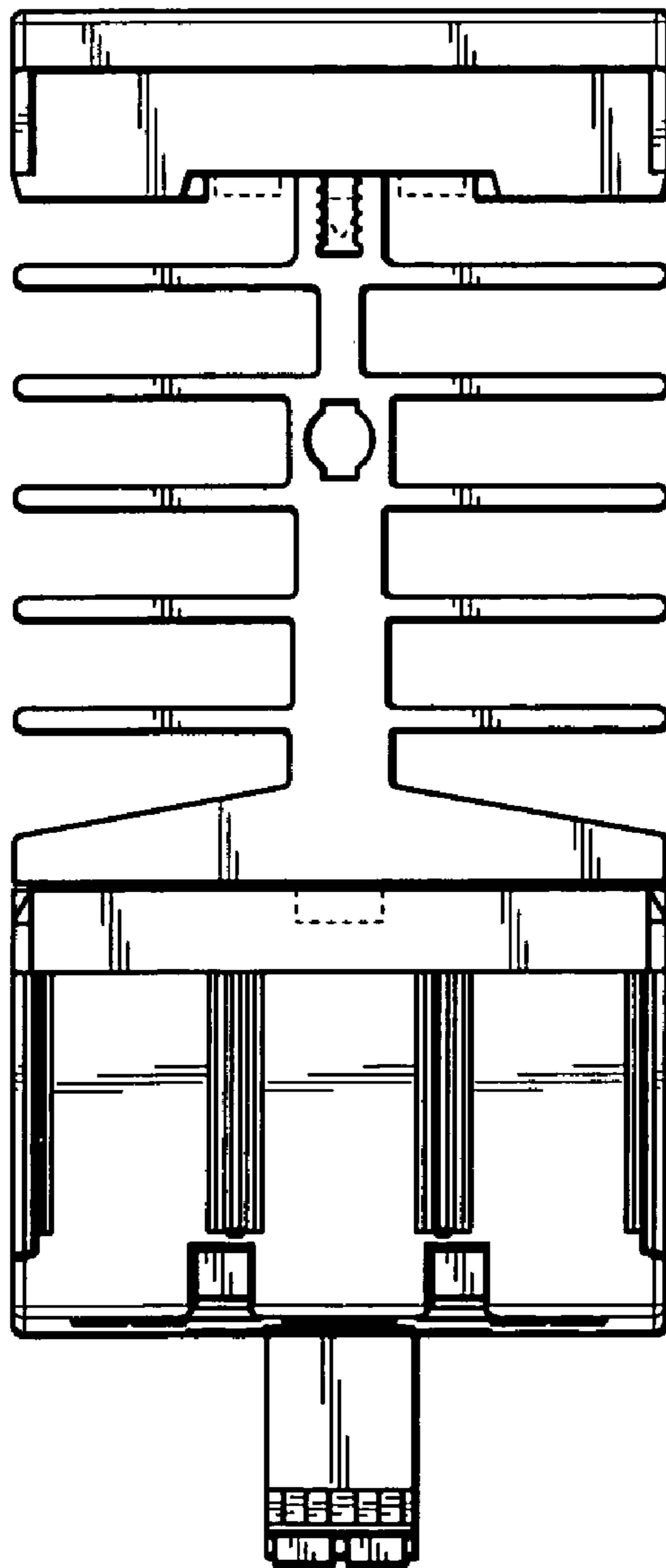


FIG 32

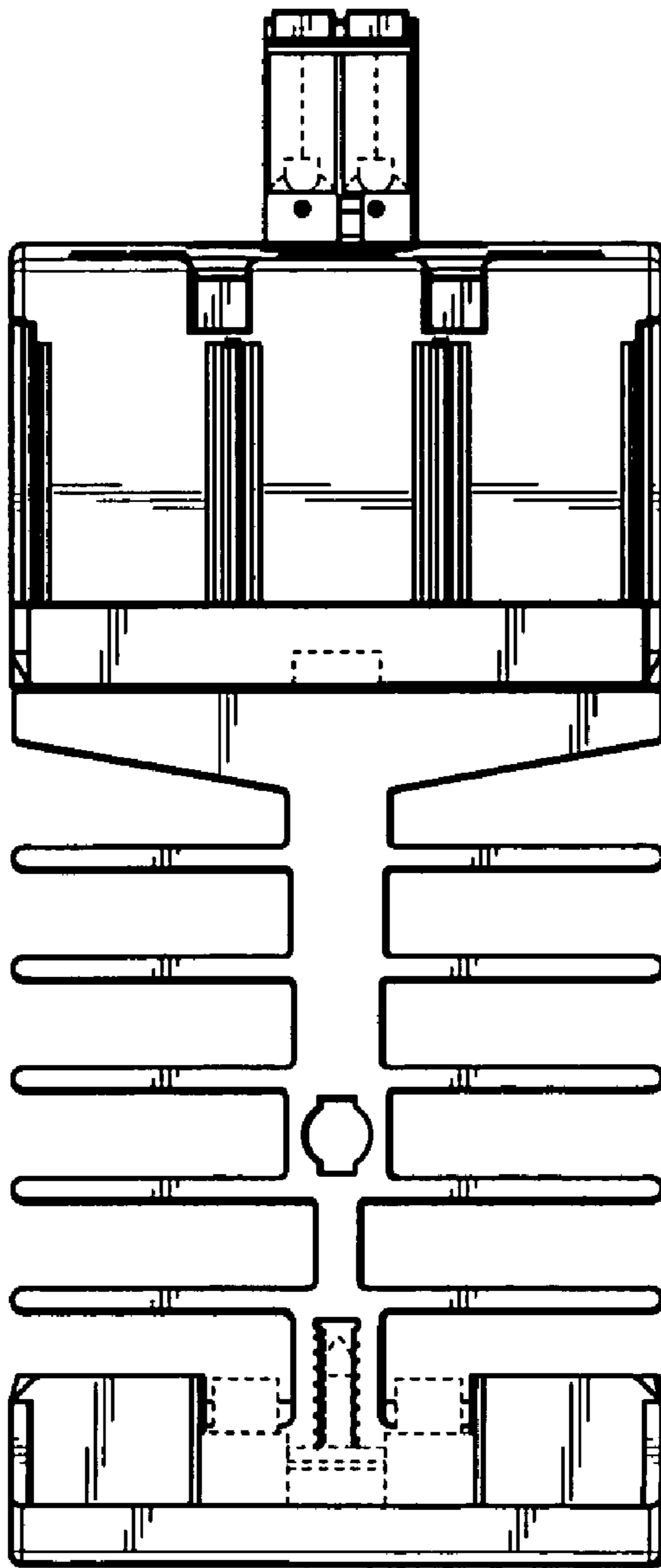


FIG 33

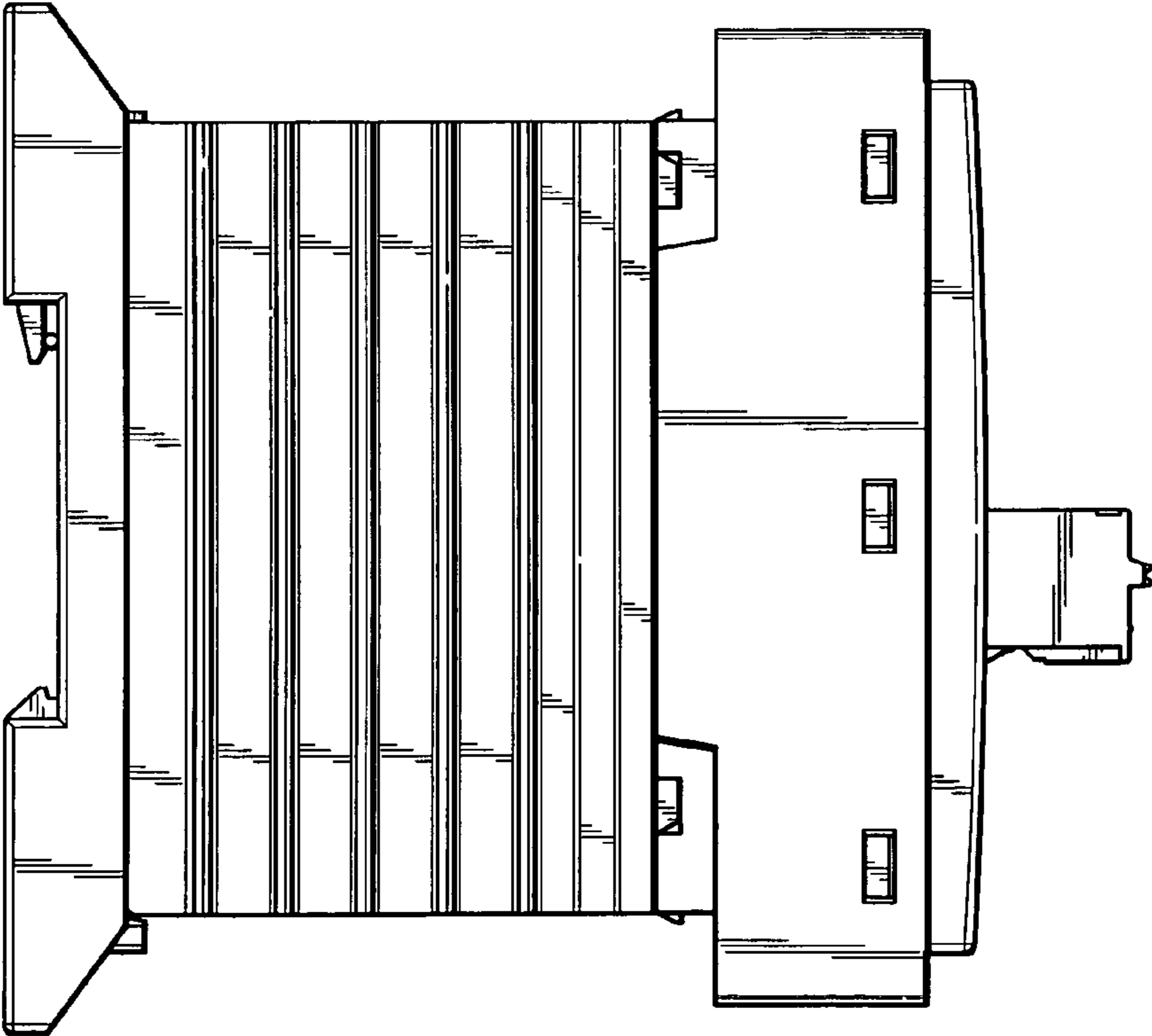


FIG 34

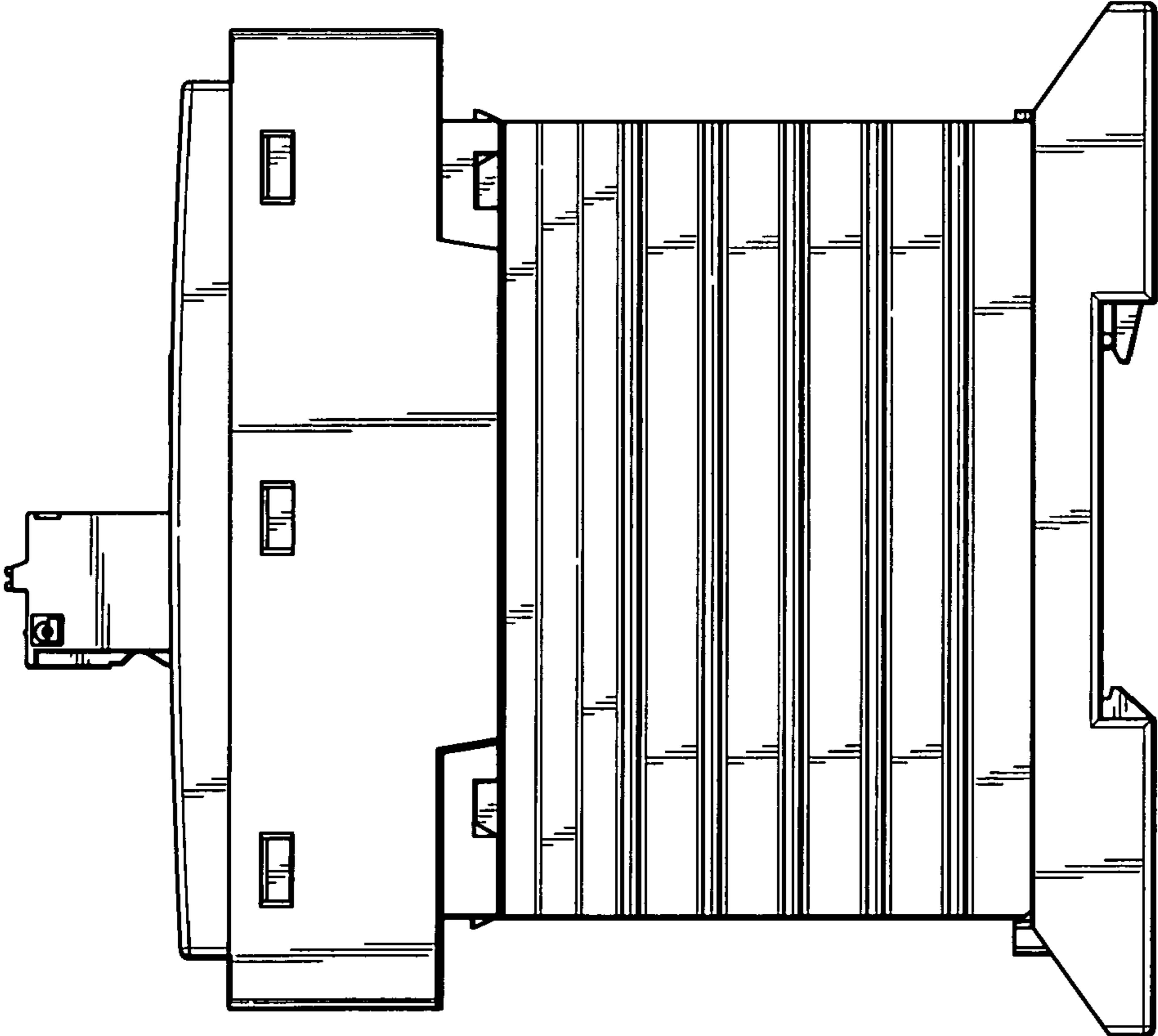


FIG 35

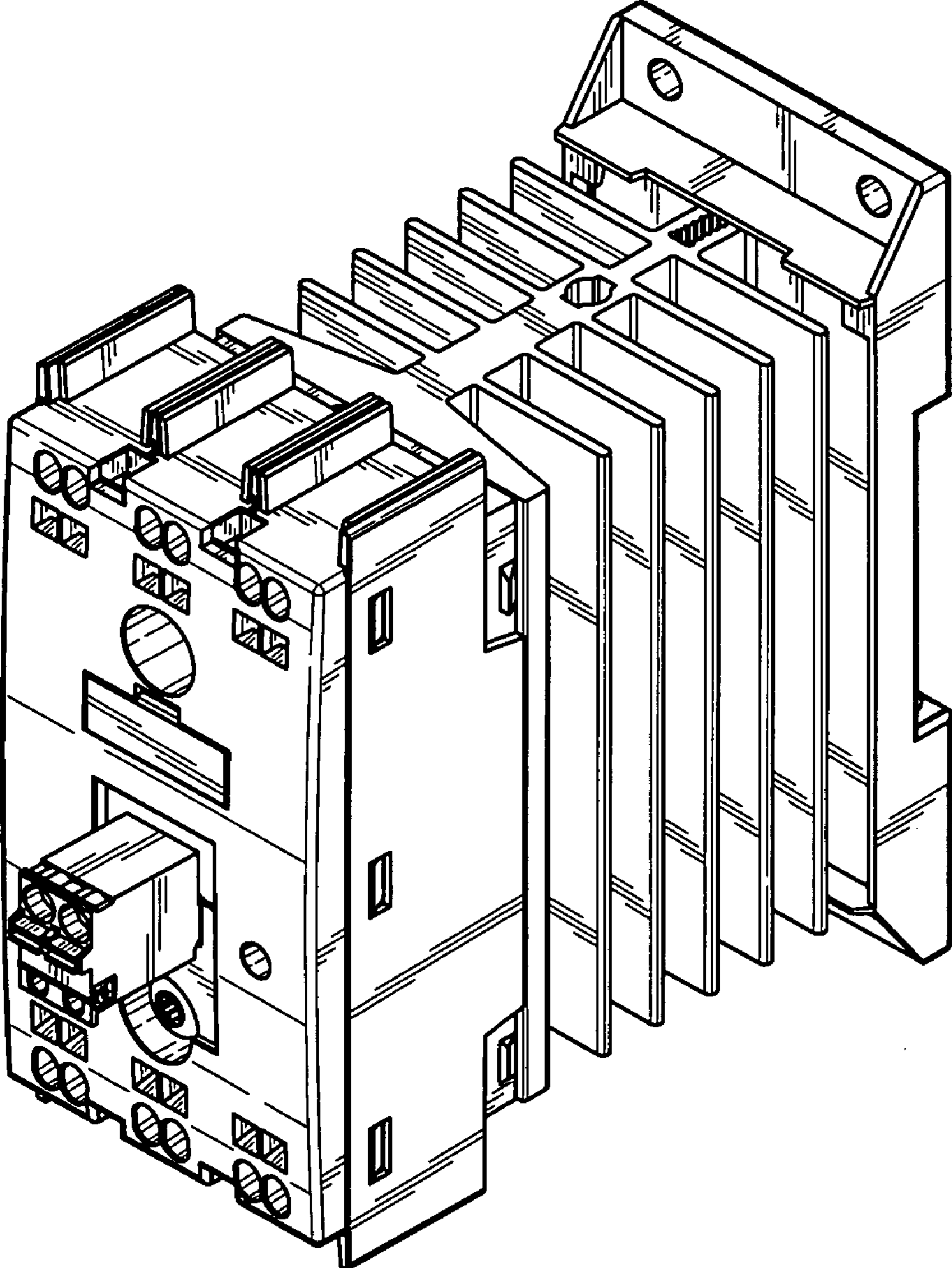


FIG 36

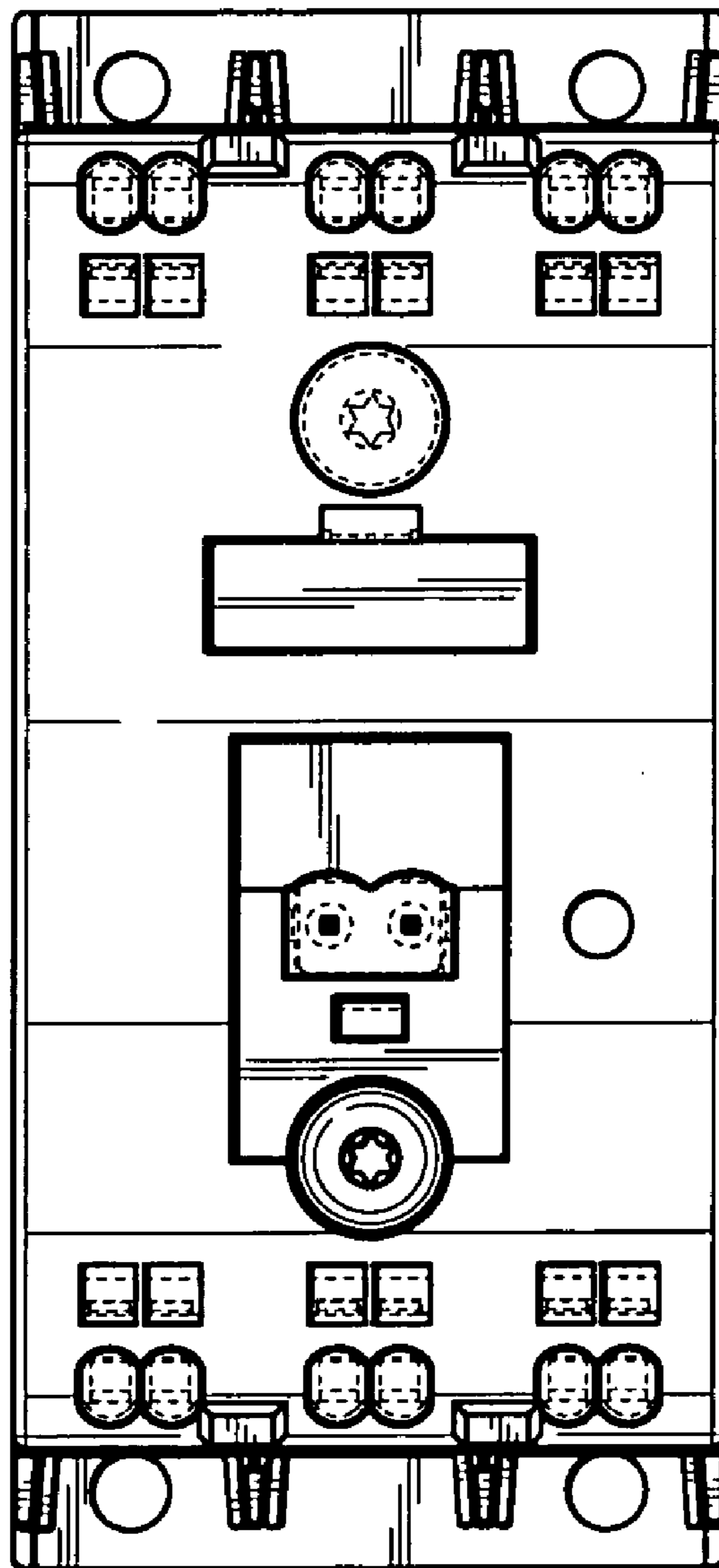


FIG 37

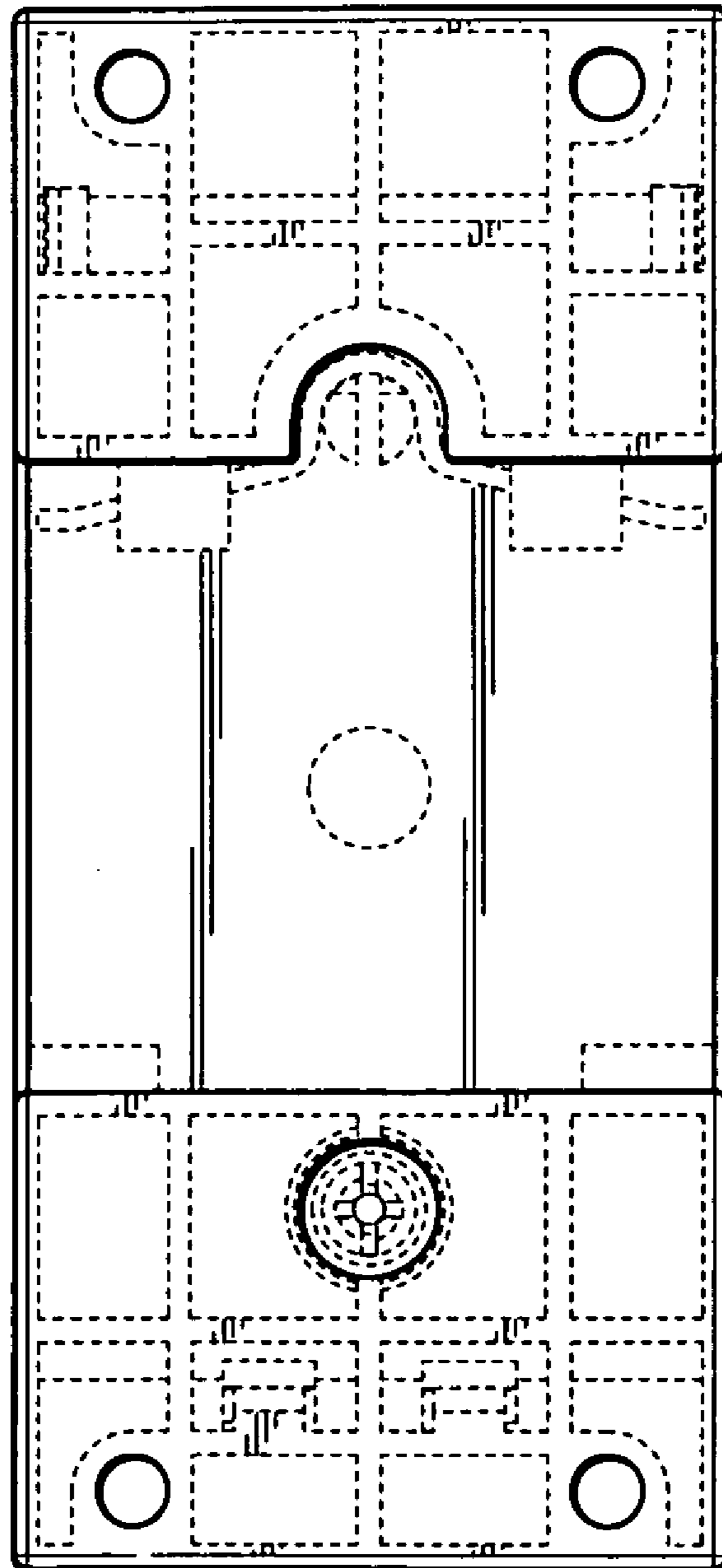


FIG 38

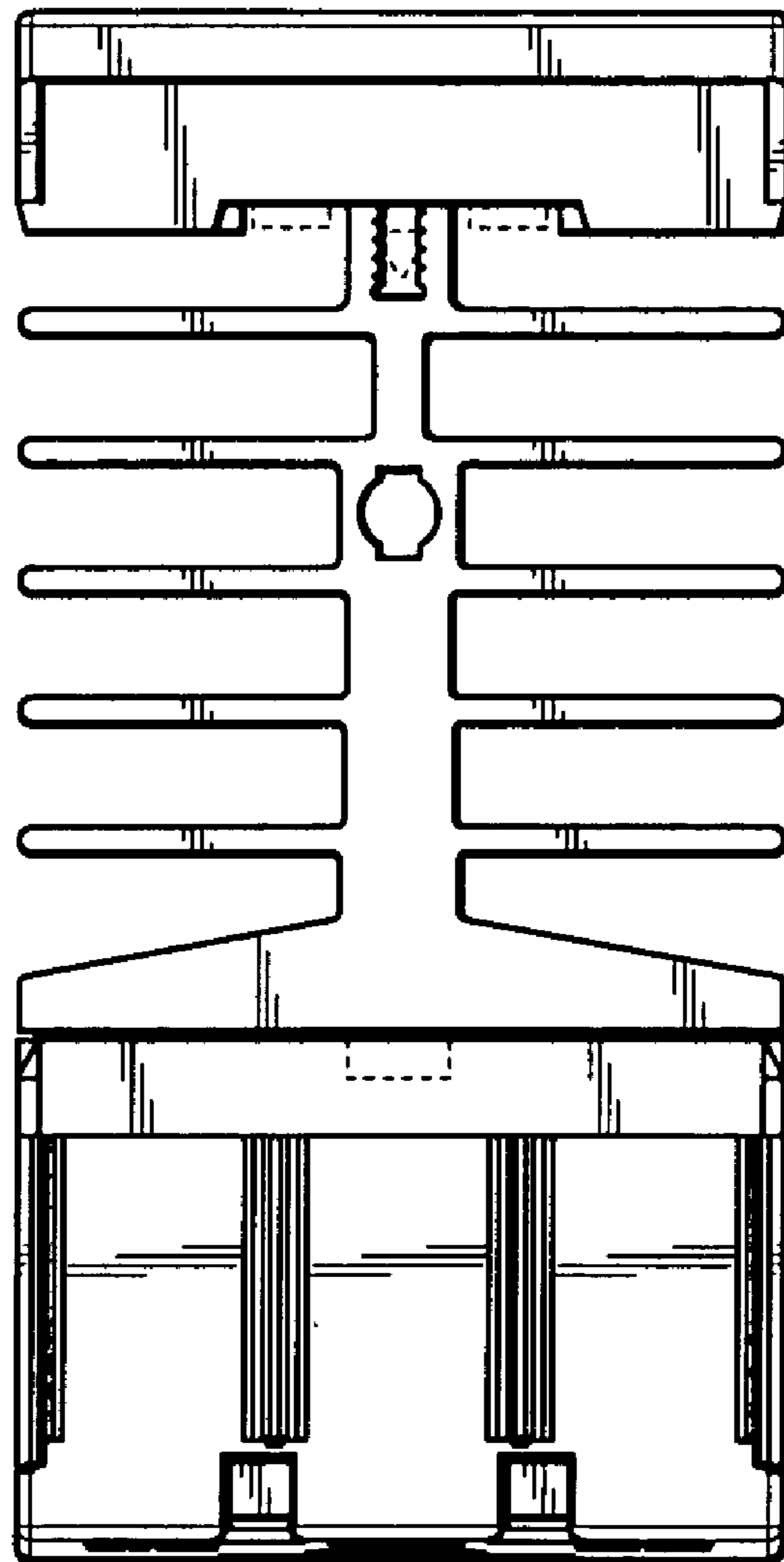




FIG 39

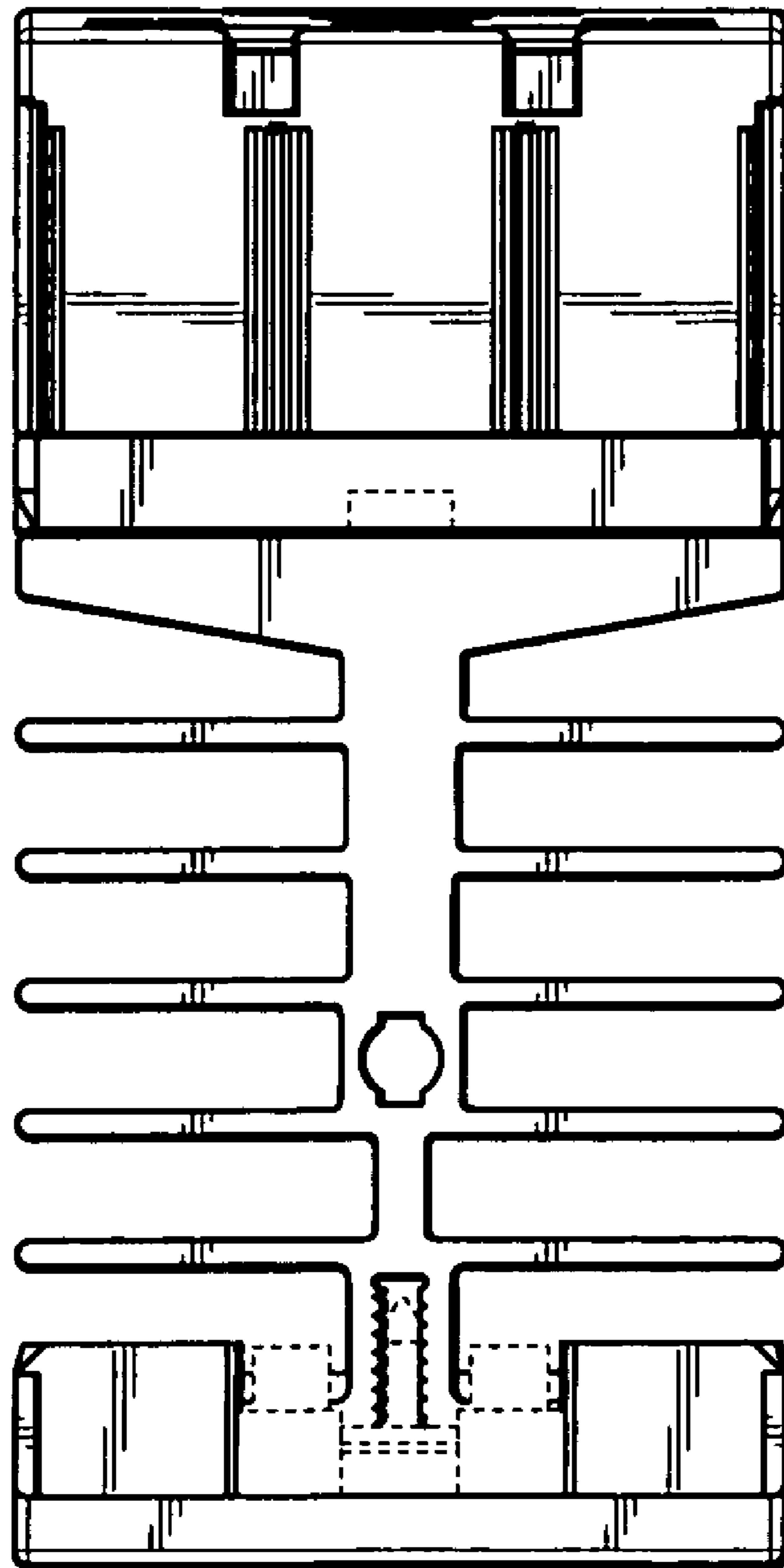


FIG 40

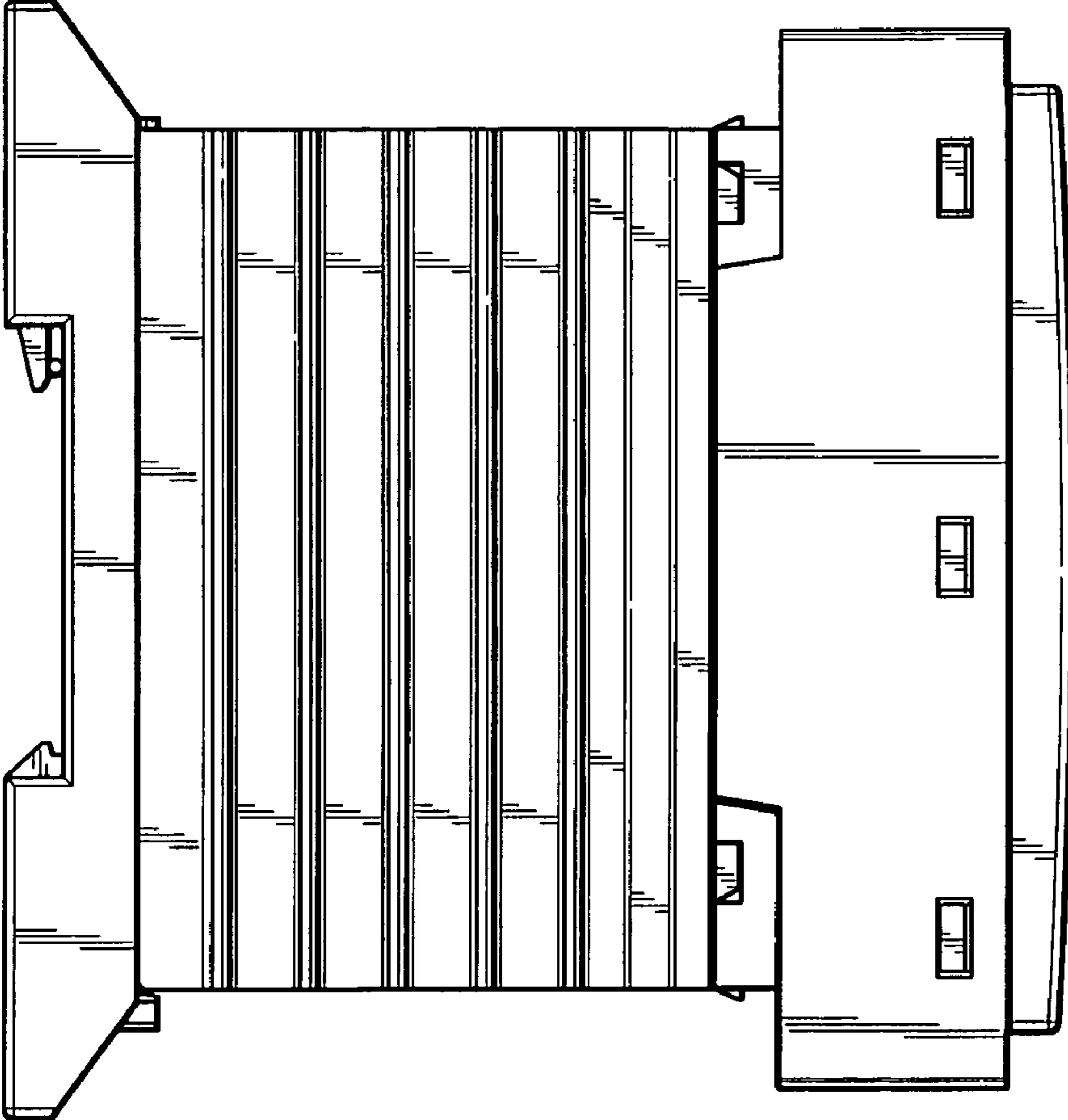


FIG 41

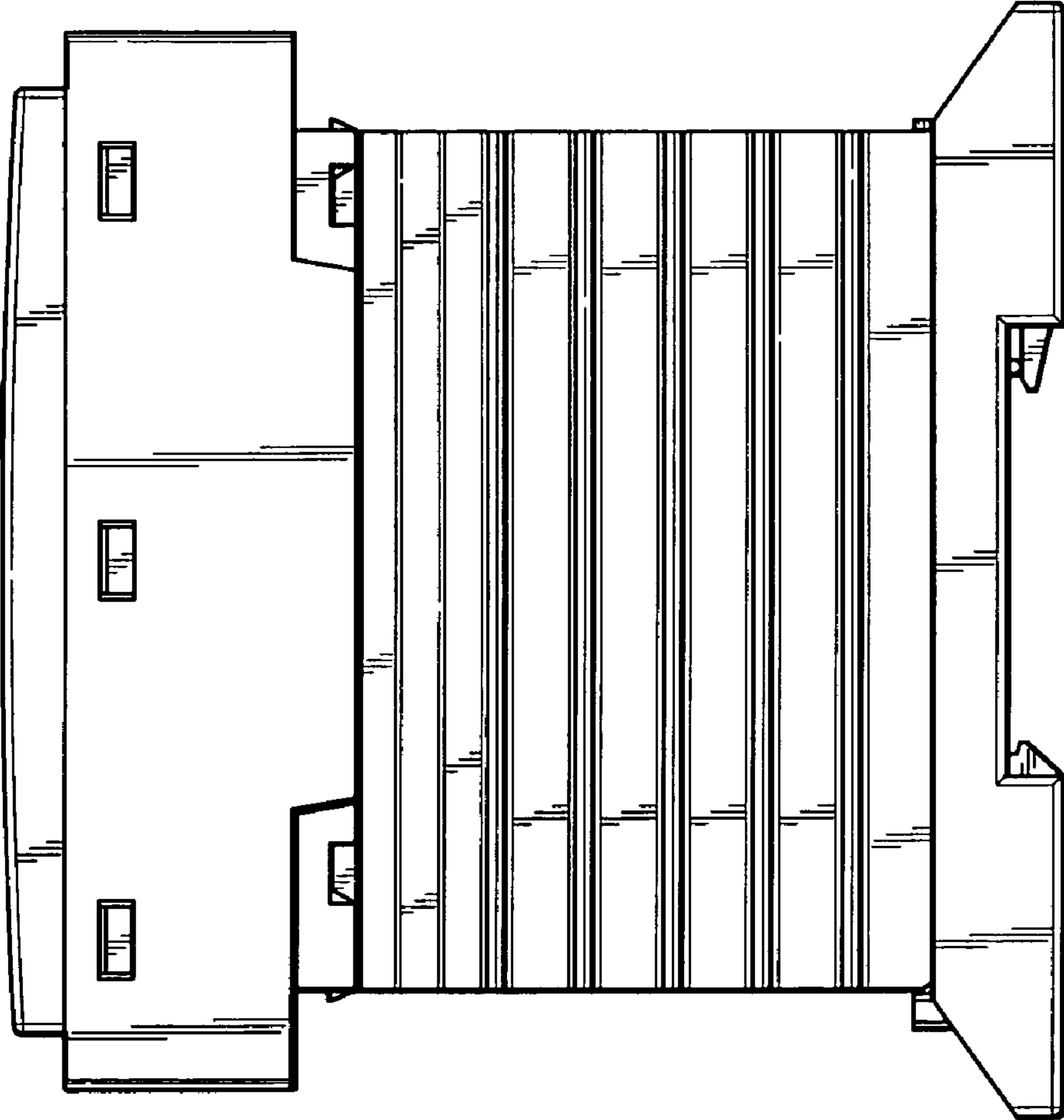


FIG 42

